武汉芯源半导体有限公司
WUHAN XINYUAN SEMICONDUCTOR CO., LTD

CW32L083 Datasheet

ARM® Cortex®-M0+ 32-bit low power MCU with up to 256KB FLASH, 24KB RAM

Rev 1.0

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1 Features

- Core: ARM® Cortex®-M0+
  - Frequency up to 64MHz
- Operating temperature: -40°C to 85°C ; Operating voltage: 1.65V to 5.5V
- Memories
  - Maximum 256 Kbytes FLASH, data retention 25 years @85°C
  - Up to 24 Kbytes RAM, support parity
  - 128 bytes OTP memory
- CRC calculation unit
- Reset and power management
  - Low power modes (Sleep, DeepSleep)
  - Power-on/ brown-out reset (POR/BOR)
  - Programmable low voltage detector (LVD)
- Clock management
  - 4 to 32 MHz crystal oscillator
  - 32kHz low speed crystal oscillator
  - Internal 48 MHz RC oscillator
  - Internal 32 kHz RC oscillator
  - Internal 10 kHz RC oscillator
  - Internal 150 kHz RC oscillator
  - Internal PLL phase-locked loop
  - Clock monitoring system
  - Allow independent shutdown of each peripheral clock
- Up to 87 I/O ports
  - All I/Os support interrupt function
  - All I/Os support interrupt input filtering
- 5-channel DMA controller
- Analog to digital converter
  - 12-bit accuracy, ±1 LSB
  - Up to 1M SPS conversion speed
  - Internel voltage reference
  - Analog watchdog function
  - Internal temperature sensor
- Dual voltage comparator

- Real Time Clock and Calendar
  - Support wakeup from Sleep/DeepSleep mode
- Timers
  - One 16-bit advanced-control timer for six-channel capture/compare and 3 pairs of complementary PWM output,dead time and flexible synchronization function
  - Four groups of 16-bit general-purpose timers
  - Three groups of 16-bit basic timers
  - A group of 16-bit ultra-low-power timers
  - 16-bit clock calibration timer
  - Window watchdog timer
  - Independent watchdog timer
- Communication interfaces
  - Six-way low-power UART with fractional baud rate
  - Two SPIs (12Mbit/s)
  - Two I2Cs (1Mbit/s)
  - IR modulator
- 4x56, 6x54 or 8x52 LCD segment code LCD driver
- TRNG true random number generator
- AES Advanced Encryption Standard Module
- Serial wire debug (SWD)
- 80-bit unique ID

Table 1-1 Package model list

Series	Model	Packages
CW32L083xC	CW32L083VC	LQFP100
	CW32L083MC	LQFP80
	CW32L083RC	LQFP64 (10mm×10mm)
		LQFP64 (7mm×7mm)
CW32L083xB	CW32L083RB	LQFP64

2 Introduction

This datasheet provides the ordering information and electromechanical characteristics of the CW32L083 microcontrollers.

This document should be read in conjunction with the CW32L083 reference manual.

For information on the Arm® Cortex®-M0+ core, please refer to the Cortex®-M0+ Technical Reference Manual, available from the *www.arm.com*.

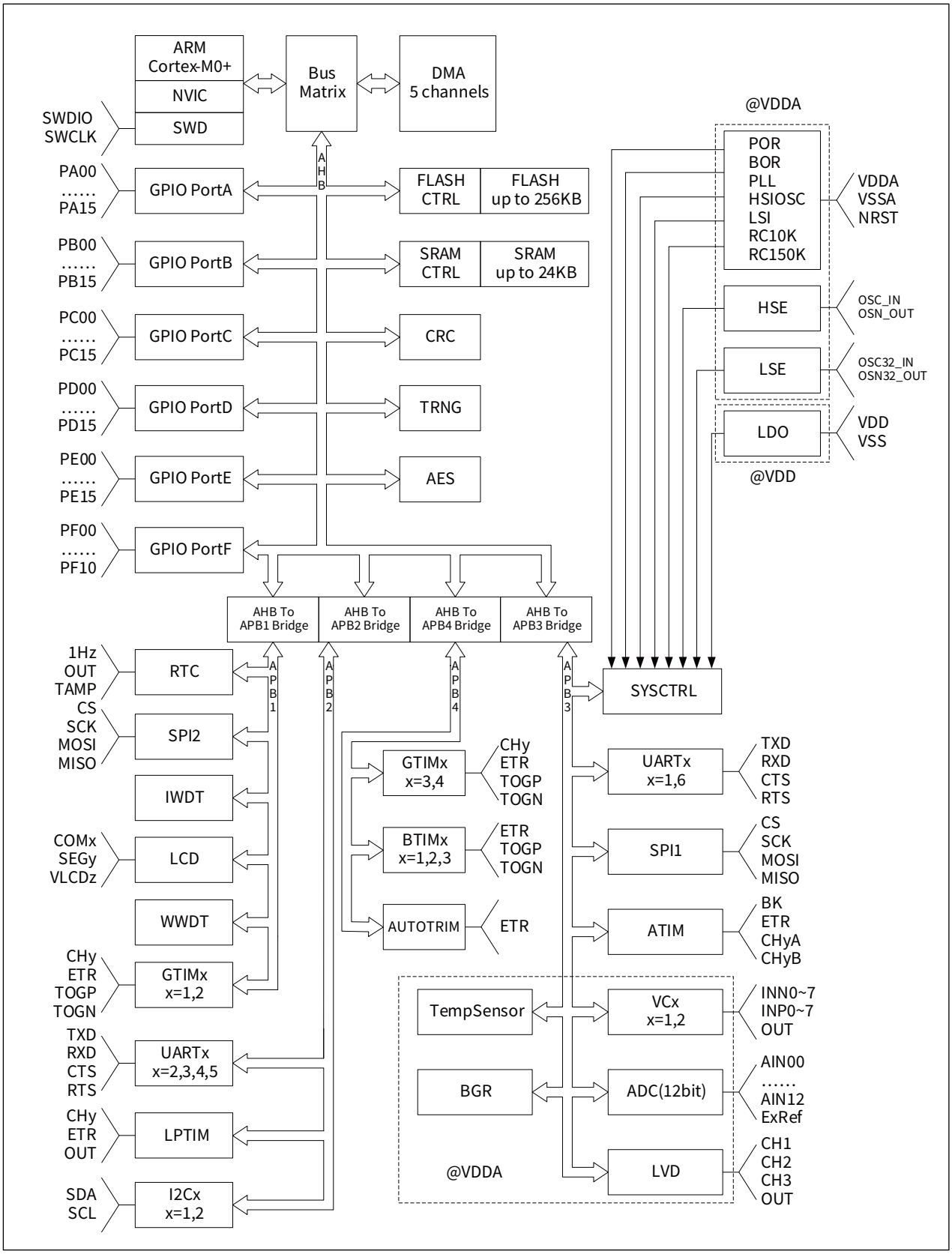
3 Description

CW32L083 is an eFlash-based single-chip Low-Power microcontroller that integrates an ARM® Cortex®-M0+ core with a main frequency up to 64MHz, high-speed embedded memories(up to 256 Kbytes of FLASH and up to 24 Kbytes of SRAM), and an extensive range of enhanced peripherals and I/Os.

All devices offer standard communication interfaces (six UARTs, two SPIs, two I2Cs), one 12-bit ADC, seven general-purpose and basic timers, an low power timers and an advanced-control PWM timers.

CW32L083 operates in the -40°C to 85°C temperature range from a 1.65 to 5.5V power supply, supports two low-power operating modes (Sleep and DeepSleep). The internal block diagram is shown in the following figure:

Figure 3-1 Internal block diagram



CW32L083 provides four different package forms: LQFP100, LQFP80, LQFP64 (10mm×10mm), LQFP64 (7mm×7mm). The functions that can be achieved by products in different packages are different. The details are shown in the following table:

Table 3-1 CW32L083 family device features list

Peripheral		CW32L083VCT6	CW32L083MCT6	CW32L083RCT6/ CW32L083RCS6	CW32L083RBT6
FLASH（Kbytes）		256	256	256	128
SRAM（Kbytes）		24	24	24	24
Timers	Advanced control	1	1	1	1
	General purpose	4	4	4	4
	Low power	1	1	1	1
	Basic	3	3	3	3
SPI		2	2	2	2
I2C		2	2	2	2
UART		6	6	6	6
12-bit ADC (number of channels)		1 (13ext. + 3 int.)	1 (13ext. + 3 int.)	1 (13ext. + 3 int.)	1 (13ext. + 3 int.)
GPIO		87	71	55	55
Kernel frequency		64MHz			
Operating voltage		1.65V ~ 5.5V			
Operating temperature		-40°C ~ 85°C			
Packages		LQFP100	LQFP80	LQFP64 (10mm×10mm)/ (7mm×7mm)	LQFP64 (10mm×10mm)

4 Functional overview

4.1 ARM® Cortex®-M0+ core with embedded Flash and SRAM

The Arm® Cortex®-M0+ processor is the latest generation 32-bit core for small embedded systems. It has been developed to provide a low-cost platform that meets the needs of MCU implementation, with a reduced pin count and low-power consumption, while delivering outstanding computational performance and an advanced system response to interrupts.

The Arm® Cortex®-M0+ 32-bit RISC processor features exceptional code-efficiency, delivering the high-performance expected from an Arm core in the small memory.

The CW32L083 family has an embedded Arm core and is therefore compatible with all Arm tools and software.

4.2 Memories

The device has the following features:

- 16 to 24 Kbytes of embedded SRAM accessed (read/write) at CPU clock speed with 0 wait states and featuring embedded parity checking with exception generation for high reliability critical applications.
- The non-volatile memory is divided into two arrays:
  - 128 to 256 Kbytes bytes of embedded Flash memory for programs and data
  - 2.5 Kbytes of boot program memory
- FLASH memory erasing and reading protection: The FLASH memory erasing and writing protection is performed through the register, and the 4-level read protection level is set through the ISP command.
  - LEVEL0

    No readout protection, the FLASH memory can be read by SWD or ISP.
  - LEVEL1

    FLASH readout protection, the FLASH memory cannot be read by SWD or ISP. The protection level can be reduced to LEVEL0 through the ISP or SWD interface. After the downgrade, the FLASH is in the whole chip erasing state.
  - LEVEL2

    FLASH readout protection, the FLASH memory cannot be read by SWD or ISP. The protection level can be reduced to LEVEL0 through the ISP interface. After the downgrade, the FLASH is in the whole chip erasing state.
  - LEVEL3

    FLASH readout protection, the FLASH memory cannot be read by SWD or ISP. Protection level downgrade in any way is not supported.

4.3 Boot mode

At startup, the BOOT pin can be used to select the following two startup options:

- Run the internal bootloader
- Run user program

When running the Bootloader, the user can use the ISP communication protocol for FALSH programming through UART1 (pins are PA13/PA14).

4.4 Cyclic redundancy check calculation unit (CRC)

The CRC calculation unit can generate the CRC code of the data stream according to the selected algorithm and parameter configuration.

Among other applications, CRC-based techniques are used to verify data transmission or storage integrity.

The product supports eight commonly used CRC algorithms, including:

CRC16_IBM
CRC16_MAXIM
CRC16_USB
CRC16_MODBUS
CRC16_CCITT
CRC16_CCITT_FALSE
CRC16_X25
CRC16_XMODEM

4.5 Power management

4.5.1 Power supply schemes

- V_{DD} = 1.65V to 5.5V
  External power supply for I/Os and the internal regulator. Provided externally through VDD pins.
- V_{DDA} = 1.65V to 5.5V
  Power supply for ADC, reset circuit, on-chip RC oscillator and PLL, connected through VDDA pin. The V_{DDA} voltage must be always greater or equal to the V_{DD} voltage.

For details about the power supply, refer to *Figure 7-3 Power system*.

4.5.2 Power supply supervisors

The product integrates power-on reset (POR) and brown-out reset (BOR) power monitoring circuits. POR and BOR are always in the working state. When the monitored power supply voltage is lower than a specific voltage threshold ($V_{POR/BOR}$), the chip keeps the reset state without external reset circuit.

The POR/BOR monitors both the VDD and VDDA supply voltages. In order to ensure that the chip works normally after the reset is released, it is necessary to ensure that VDD/VDDA is powered on and off at the same time in the circuit design.

4.5.3 Voltage regulator

The internal voltage regulator has "normal" and "low power" operating modes, and it always enabled after reset.

- The "normal" mode corresponds to a state of full speed operation.
- The "low-power" mode corresponds to some power supply working states, including Sleep and DeepSleep working modes.

4.5.4 Low-power modes

The CW32L083 microcontrollers support two low-power modes:

- Sleep mode
  In Sleep mode, only the CPU is stopped. All peripherals continue to operate and can wake up the CPU when an interrupt/event occurs.
- DeepSleep mode
  DeepSleep is used to achieve the lowest power consumption, the CPU stops running, the high-speed clock modules (HSE, HSIOSC) are automatically turned off, and the low-speed clocks (LSE, LSI, RC10K, RC150K) remain unchanged.
  The device exits DeepSleep mode when an external reset, or an IWDT reset, or some peripheral interrupts, or an RTC event occurs.

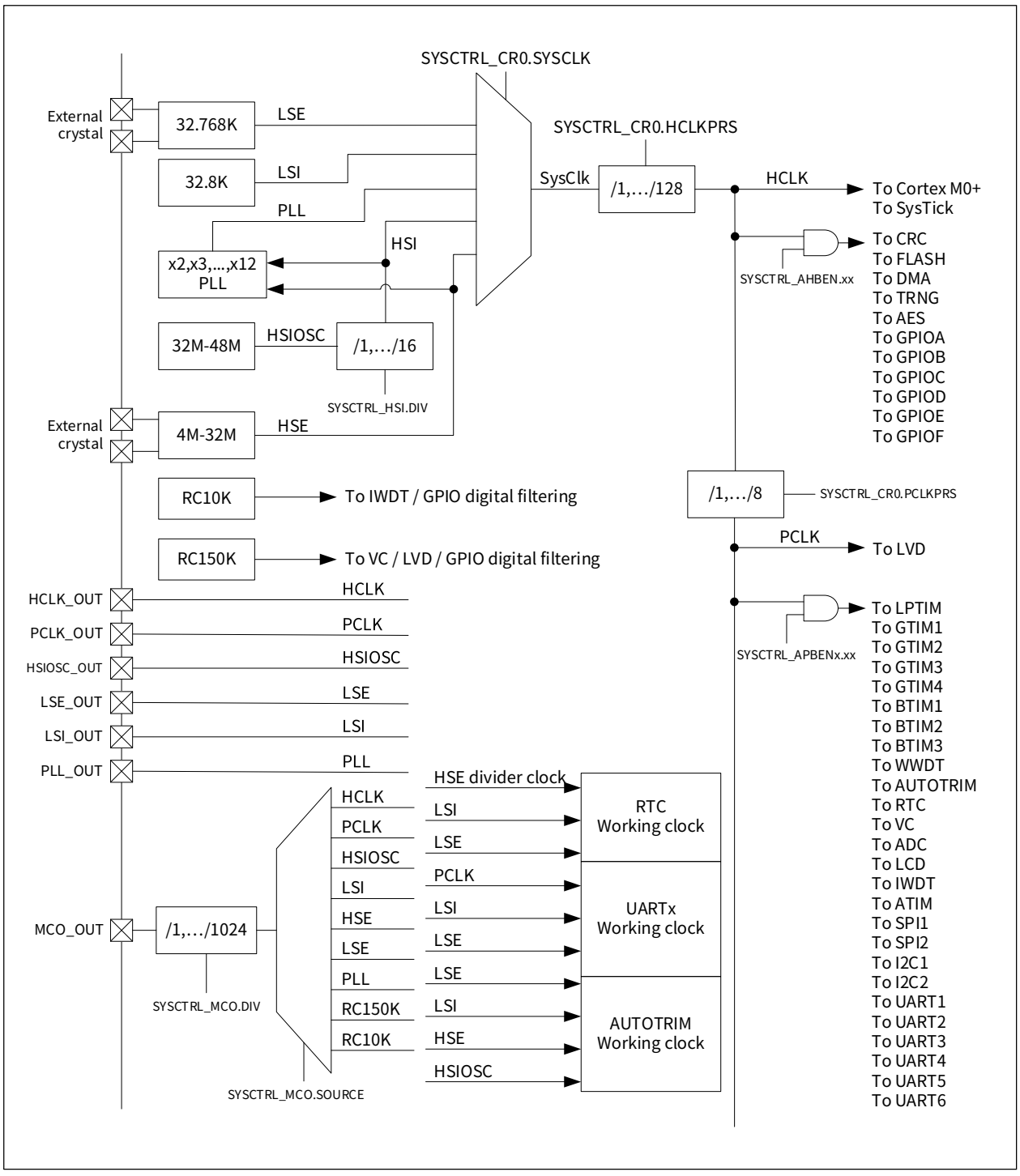
4.6 Clocks and startup

After the MCU is reset, the HSI (generated by the internal 48MHz HSIOSC oscillator frequency division) is selected as the clock source of SysClk by default, and the default value of the system clock frequency is 8MHz.The user can use the program to start the external crystal oscillator and switch the system clock source to the external clock source. The clock failure detection module can continuously detect the state of the external clock source. Once the failure of the external clock source is detected, the system will automatically switch to the internal HSIOSC clock source. If the corresponding fault detection interrupt is enabled, an interrupt will be generated for the user to record fault events.

Several prescalers allow the application to configure the frequency of the AHB and the APB domains. The maximum frequency of the AHB and the APB domains is 64 MHz.

The internal clock tree of the system is shown below :

Figure 4-1 Clock tree of CW32L083



4.7 General-purpose inputs/outputs (GPIO)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function. Some GPIO pins have analog functions and interface with internal analog peripherals. All I/Os can be configured as external interrupt input pins and have digital filtering.

The I/O configuration can be locked to prevent program misoperation and improve security.

4.8 Direct memory access controller (DMA)

The chip has a built-in DMA controller, 5 independent channels, high-speed data transmission between peripherals and memory, between peripherals and peripherals, and between memory and memory.

Each channel is connected to dedicated hardware DMA requests, with support for software trigger on each channel. The software can configure the transmission direction and data length of each channel individually.

4.9 Nested vectored interrupt controller (NVIC)

The CW32L083 family embeds a nested vectored interrupt controller able to handle up to 32 maskable interrupt channels (not including the 16 interrupt lines of Cortex®-M0+) and supports programmable 4 priority levels.

- Interrupt entry vector table address can be remapped
- Closely coupled NVIC core interface
- Processing of late arriving higher priority interrupts
- Support for tail-chaining
- Processor state automatically saved

This hardware block provides flexible interrupt management features with minimal interrupt latency.

4.10 Analog to digital converter (ADC)

The internal 12-bit analog to digital converter has up to 13 external and three internal (temperature sensor, voltage reference measurement, VDDA/3) channels and performs conversions in single-shot or scan modes.

In scan mode, automatic conversion is performed on a selected group of analog inputs.

High-precision voltage reference can be externally connected.

The ADC can be served by the DMA controller.

An analog watchdog feature allows very precise monitoring of the converted voltage of a selected channel. An interrupt is generated when the converted voltage is outside the programmed thresholds.

4.10.1 Temperature sensor

The temperature sensor (TS) generates a voltage V_{SENSE} that varies linearly with temperature.

The temperature sensor is internally connected to the ADC_IN14 input channel which is used to convert the sensor output voltage into a digital value.

The sensor provides good linearity but it has to be calibrated to obtain good overall accuracy of the temperature measurement. As the offset of the temperature sensor varies from chip to chip due to process variation, the uncalibrated internal temperature sensor is suitable for applications that detect temperature changes only.

To improve the accuracy of temperature sensor measurement, manufacturers perform individual factory calibrations for each chip. Temperature sensor factory calibration data is stored in FLASH memory.

Table 4-1 Internal temperature sensor calibration value address

ADC reference voltage	Calibration value storage address	Calibration value accuracy
Internal 1.5V	0x0010 0A0A - 0x0010 0A0B	±3°C
Internal 2.5V	0x0010 0A0C - 0x0010 0A0D	±3°C

4.10.2 Internal voltage reference

In addition to VDDA and external reference voltage, ADC reference voltage can also choose internal reference voltage. The internal reference voltage generator (BGR) can provide stable voltage output for ADC, which is 1.5V and 2.5V respectively.

4.11 Analog voltage comparator (VC)

Two analog voltage comparators (VC) are integrated inside, which are used to compare two analog input voltages and output the comparison results from the pins. The positive terminal input of the voltage comparator supports up to 8 external analog inputs, and the negative terminal supports not only 8 external analog inputs, but also internal voltage reference, internal resistance voltage divider, internal temperature sensor and other voltage references. The comparison result output has filtering function, hysteresis window function, and polarity selection. Support compare interrupt, which can be used to wake up MCU in low power mode.

The main features of an analog voltage comparator (VC) are:

- Dual analog voltage comparator VC1、VC2
- Internal 64-step resistor divider
- Up to 8 external analog signal inputs
- 4 on-chip analog input signals
  - Built-in Resistor Divider Output Voltage
  - Built-in temperature sensor output voltage
  - Built-in 1.2V reference voltage
  - ADC reference voltage
- Selectable output polarity
- Support hysteresis window compare function
- Programmable filters and filter times
- 3 interrupt triggering methods, which can be used in combination
  - High level trigger
  - Rising edge trigger
  - Falling edge trigger
- Support running in low power mode, interrupt wake-up MCU

4.12 Low voltage detector (LVD)

Low Voltage Detector (LVD) is used to monitor the VDDA power supply voltage or external pin input voltage. When the comparison results between the monitored voltage and the LVD threshold meets the trigger condition, an LVD interrupt or reset signal will be generated, which is usually used to handle some urgent tasks.

The interrupt and reset flags generated by the LVD can only be cleared by software; only after the interrupt or reset flag is cleared and the trigger condition is reached again, the LVD can generate an interrupt or reset signal again.

The main features of a low voltage detector (LVD) are:

- 4-channel monitoring voltage source: VDDA power supply voltage, PA00, PB00, PB11 pin input
- 16-step threshold voltage, range 1.8V~3.3V
- 3 trigger conditions, which can be used in combination
  - Level Triggered: Voltage Below Threshold
  - Falling edge trigger: the falling edge when the voltage falls below the threshold
  - Rising edge trigger: the rising edge when the voltage rises back above the threshold
- Can trigger to generate interrupt or reset signal, both cannot be generated at the same time
- 8-step filter configurable
- Support hysteresis function
- Support running in low power mode, interrupt wake-up MCU

4.13 Timers and watchdogs

The CW32L083 microcontroller integrates up to four general-purpose timers, three basic timers , one low power timer and one advanced control timer.

The function differences of different timers are shown in the following table:

Table 4-2 Timer feature comparison

Timer type	Timer	Counter resolution	Counter type	Prescaler factor	DMA request generation	Capture/compare channels	Complementary outputs
Advanced control	ATIM	16-bit	Up, down, up/do wn	2^N(N=0,..,7)	YES	6	3
General purpose	GTIM1	16-bit	Up, down, up/down	1,2,3,4,⋯,65536	YES	4	1
	GTIM2	16-bit	Up, down, up/down	1,2,3,4,⋯,65536	YES	4	1
	GTIM3	16-bit	Up, down, up/down	1,2,3,4,⋯,65536	YES	4	1
	GTIM4	16-bit	Up, down, up/down	1,2,3,4,⋯,65536	YES	4	1
Low power	LPTIM	16-bit	Up, down, up/down	2^N(N=0,..7)	NO	2	0
Basic	BTIM1	16-bit	Up	1,2,3,4,⋯,65536	YES	0	1
	BTIM2	16-bit	Up	1,2,3,4,⋯,65536	YES	0	1
	BTIM3	16-bit	Up	1,2,3,4,⋯,65536	YES	0	1

4.13.1 Advanced-control timer (ATIM)

The Advanced-control Timer (ATIM) consists of a 16-bit auto-reload counter and 7 compare units, driven by a programmable prescaler. ATIM supports 6 independent capture/compare channels, which can realize 6 independent PWM outputs or 3 pairs of complementary PWM outputs or capture 6 inputs. Can be used for basic timing/counting, measuring pulse width and period of input signals, generating output waveforms (PWM, single pulse, complementary PWM with dead time inserted, etc.).

4.13.2 General-purpose timers (GTIM1..4)

Four general-purpose timers (GTIMs) are integrated inside. Each GTIM is completely independent and has the same function. Each includes a 16-bit automatic reloading counter and is driven by a programmable prescaler. GTIM supports 4 basic working modes: timer mode, counter mode, trigger start mode and gate control mode. Each group has 4 independent capture/compare channels, which can measure the pulse width of input signals (input capture) or generate output waveforms (output compare and PWM).

4.13.3 Low power timer (LPTIM)

A 16-bit low-power timer (LPTIM) is integrated inside, which can realize the function of timing or counting external pulses with very low power consumption. By selecting an appropriate clock source and trigger signal, the function of waking up the system when it is in low-power sleep mode can be realized. There is a compare register inside the LPTIM, which can realize the compare output and PWM output, and can control the polarity of the output waveform. In addition, LPTIM can also be connected with a quadrature encoder to automatically count up and down.

4.13.4 Basic timers (BTIM1..3)

Three basic timers (BTIM) are integrated inside, each BTIM is completely independent and has the same function, each contains a 16-bit automatic reloading counter and is driven by a programmable prescaler. BTIM supports four working modes: timer mode, counter mode, trigger start mode and gate control mode, and supports overflow event trigger interrupt request and DMA request. Thanks to the fine processing design of the trigger signal, the BTIM can automatically perform the filtering operation of the trigger signal by the hardware, and can also cause the trigger event to generate interrupts and DMA requests.

4.13.5 Independent watchdog (IWDT)

The Independent Watchdog Timer (IWDT) uses a dedicated internal RC clock source, RC10K, to avoid external influences during operation. Once the IWDT is started, the user needs to reload the counter of the IWDT within a specified time interval, otherwise an overflow will trigger a reset or generate an interrupt signal. After the IWDT is started, the counting can be stopped. The user can choose to keep the IWDT running or suspend counting while in DeepSleep mode.

A specially set key-value register can lock the key registers of the IWDT to prevent the registers from being accidentally modified.

4.13.6 System window watchdog (WWDT)

The CW32L083 microcontroller integrates a window watchdog timer (WWDT), the user needs to refresh within the set time window, otherwise the watchdog overflow will trigger a system reset. WWDT is usually used to monitor the program execution flow with strict time requirements to prevent the abnormal execution of the application program caused by external interference or unknown conditions, resulting in system failure.

4.13.7 SysTick timer

This timer is dedicated to real-time operating systems, but could also be used as a standard down counter. It features:

- A 24-bit down counter
- Autoreload capability
- Maskable system interrupt generation when the counter reaches 0

4.14 Clock calibration timer (AUTOTRIM)

The clock calibration timer (AUTOTRIM) has 2 working modes: Automatic wake-up timer mode and clock calibration timer mode. In automatic wake-up timer mode, it has a general timing function and can choose from 5 counting clock sources. When the counter clock source is LSE or LSI, it can keep running in DeepSleep mode, and the counter underflow interrupt can wake up the MCU and return to Active mode. In clock calibration timer mode, it supports HSIOSC/LSI automatic real-time calibration and automatic single calibration, so that the accuracy of HSIOSC/LSI output frequency is no longer affected by environmental changes.

4.15 Real-time clock (RTC)

The Real Time Clock (RTC) is a dedicated counter/timer that provides calendar information including hours, minutes, seconds, date, month, year, and week day.

RTC has two independent alarm clocks, the time and date can be set in combination, and the alarm clock interrupt can be generated and output through the pin; it supports the time stamp function, which can be triggered by the pin, record the current date and time, and generate a time stamp interrupt at the same time; Support periodic interrupt; support automatic wake-up function, which can generate interrupts and output through pins; support 1Hz square wave and RTCOUT output functions; support internal clock calibration compensation.

The CW32L083 has internal independently calibrated RC clock source with a frequency of 32kHz to provide the drive clock for the RTC. The RTC can run in DeepSleep mode and is suitable for applications requiring low power consumption.

4.16 Inter-integrated circuit interfaces (I2C)

The I2C controller can serially send the data to be sent to the I2C bus according to the I2C specification according to the set transmission rate (standard, fast, high-speed), and detect the state during the communication process. I2C also support bus conflict and arbitration handling in multi-master communication.

The main features of the I2C controller are:

- Supports master send/receive and slave send/receive four working modes
- Supports clock stretching (clock synchronization) and multi-master communication collision arbitration
- Supports standard (100Kbps)/fast (400Kbps)/high speed (1Mbps) three working rates
- Supports 7-bit addressing mode
- Supports 3 slave addresses
- Supports broadcast address
- Supports input signal noise filtering function
- Supports interrupt status query function

4.17 Universal asynchronous receiver/transmitter (UART)

Universal asynchronous receiver/transmitter (UART) supports asynchronous full-duplex, synchronous half-duplex and single-wire half-duplex modes, supports hardware data flow control and multi-machine communication; the data frame structure is programmable, and a wide range of baud rate selection can be provided through the fractional baud rate generator.

The UART controller works in a dual clock domain, allowing data reception in DeepSleep mode, and the reception completion interrupt can wake the MCU back to Active mode.

4.18 Serial peripheral interface (SPI)

Serial Peripheral Interface (SPI) supports bidirectional full-duplex, single-wire half-duplex and simplex communication modes, MCU can be configured as master or slave, multi-master communication mode is supported, and direct memory access (DMA) is supported.

The main features of the Serial Peripheral Interface (SPI) are:

- Supports master mode, slave mode
- Supports full-duplex, single-wire half-duplex, simplex
- 4-bit to 16-bit selectable data frame width
- Supports sending and receiving data LSB or MSB first
- Clock Polarity and Clock Phase is programmable
- Communication rates up to PCLK/2 in master mode
- Communication rates up to PCLK/4 in slave mode
- Supports multi-machine communication mode
- 8 interrupt sources with flag bits
- Supports Direct Memory Access (DMA)

4.19 Infrared modulation transmitter (IR)

The built-in infrared modulation transmitter (IR) can be used in conjunction with UART through two general-purpose timers or one general-purpose timer, which can easily implement various standard PWM or PPM encoding methods, and can also realize infrared modulation and transmission of UART data.

The main characteristics of the infrared modulation transmitter (IR) are:

- SIR supporting IrDA Standard 1.0
- Maximum data rate 115.2kbps
- Can adapt to high and low level infrared emission tube

4.20 True random number generator (TRNG)

The True Random Number Generator (TRNG) uses an internal analog random source to generate 64-bit true random numbers through a specific configuration mode.

The main features of a True Random Number Generator (TRNG) are:

- 64-bit true random number
- 3 kinds of True Random Number Generation Configurations
- can be disabled to reduce power consumption

4.21 Advanced encryption standard module (AES)

The Advanced Encryption Standard Module (AES) can be used to encrypt and decrypt data through the AES algorithm. AES supports 128-bit block processing and supports key lengths of 128, 192 or 256 bits.

The main features of Advanced Encryption Standard Module (AES) are:

- Encrypt/Decrypt using AES algorithm
- 128-bit data block processing
- 128-bit, 192-bit, 256-bit key length
- Support Electronic Code Book (ECB)

4.22 LCD controller (LCD)

The liquid crystal controller is used for digital control and driving of monochrome passive liquid crystal display (LCD), with up to 8 common terminals (COM) and 56 segment terminals (SEG), which can drive 224 (4×56), 324 (6 ×54) or 416 (8×52) LCD picture elements.

The main features of the liquid crystal controller (LCD) are:

- Highly flexible frame rate control
- Supports Static, 1/2, 1/3, 1/4, 1/6 and 1/8 Duty Cycles
- Support 1/2, 1/3 offset
- 16-level contrast adjustment
- 3 kinds of bias voltage generation modes: internal resistor divider, external resistor divider, and external capacitor divider
- Internal Resistor Divider Adjustable by Software
- Built-in charge pump circuit
- Support frame interrupt
- Support DMA transfer
- Support LCD flicker function, flicker frequency can be configured
- Unused LCD segments and common pins can be configured as digital or analog functions

4.23 Serial wire debug port (SWD)

An ARM SWD interface is provided, and users can use the CW-DAPLINK of Xinyuan Semiconductor to connect to the MCU to debug and simulate in the IDE development environment.

5 Pin descriptions

Figure 5-1 LQFP100 package pinout (top view)

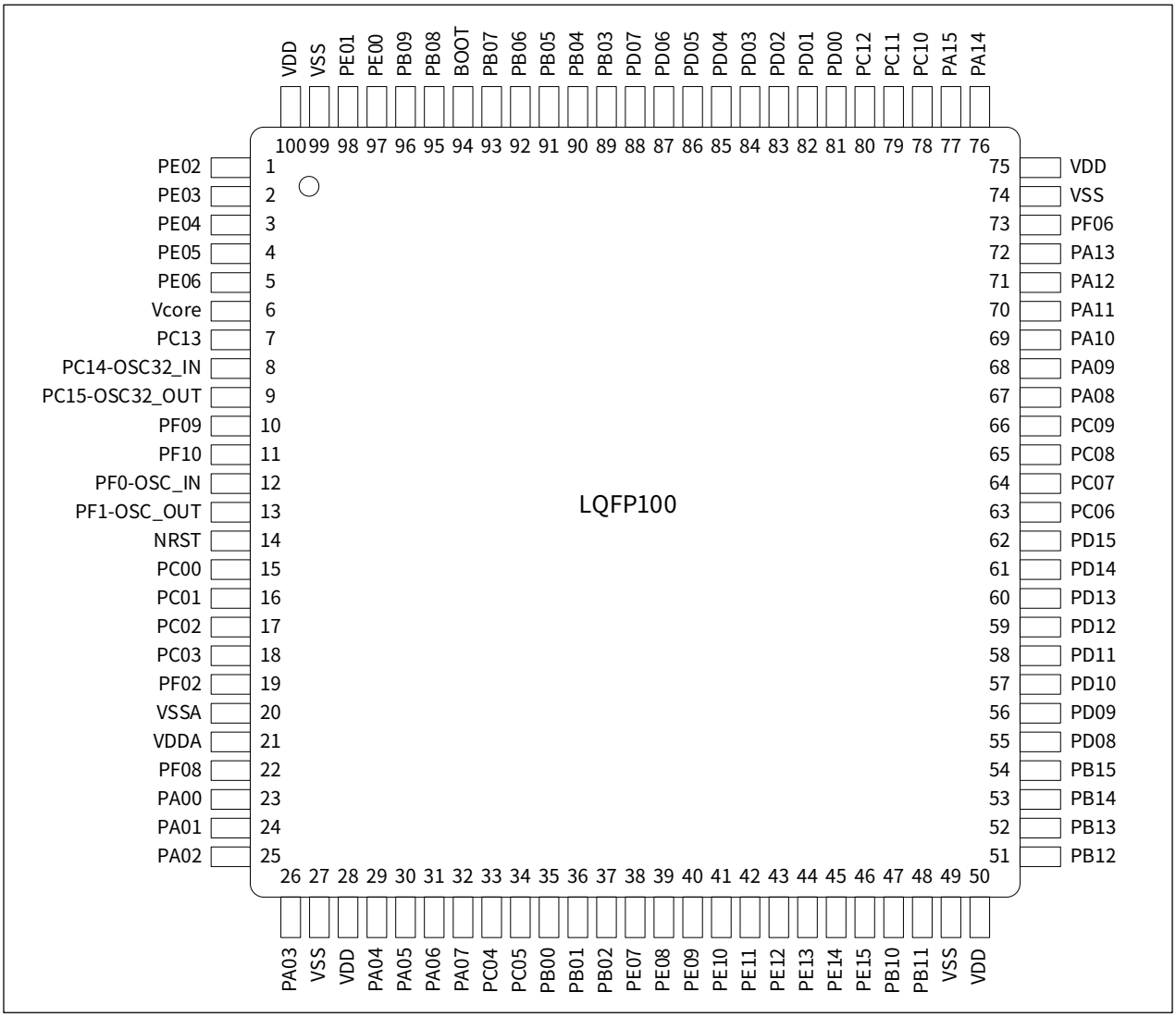


Figure 5-2 LQFP80 package pinout (top view)

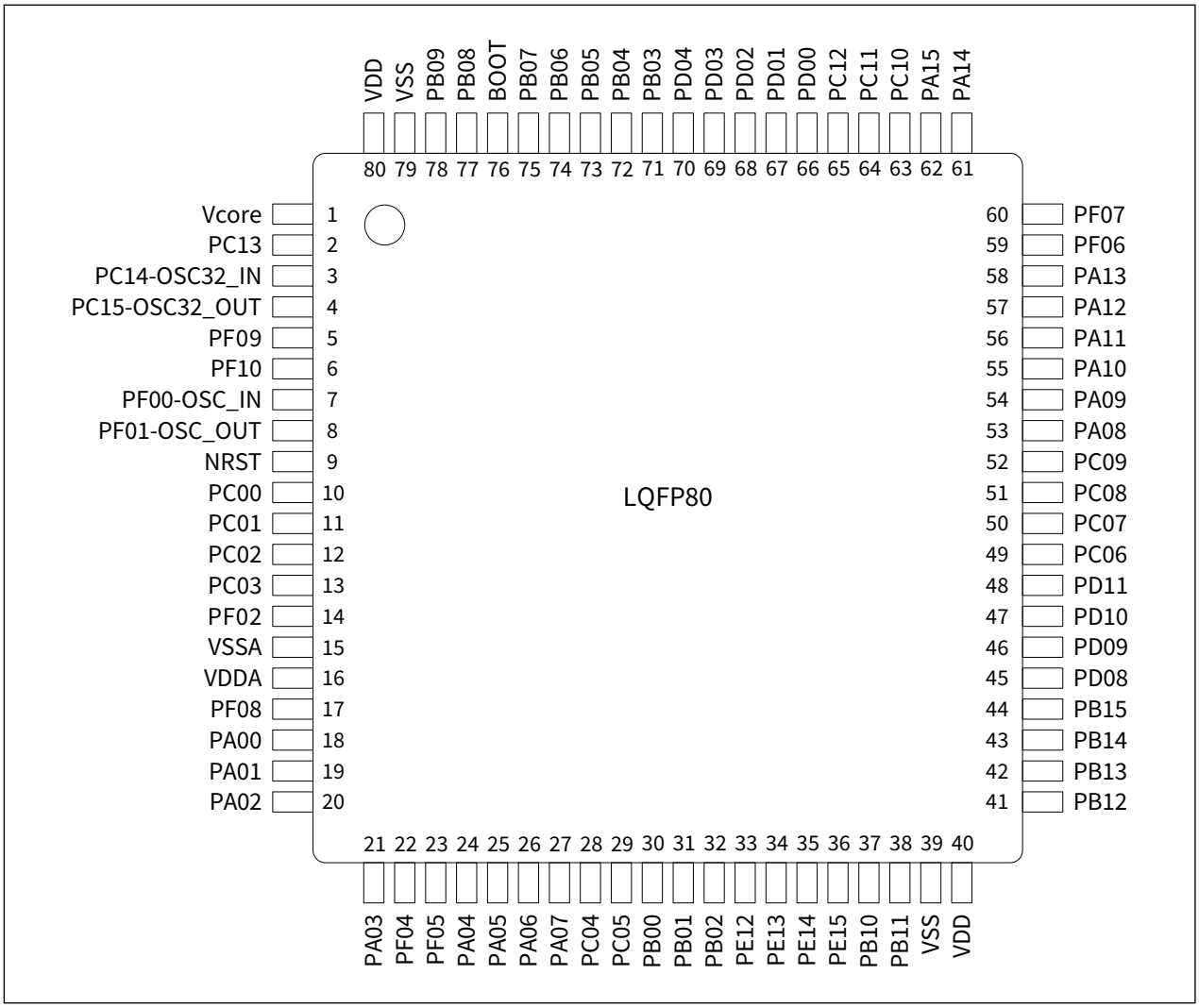


Figure 5-3 LQFP64 package pinout (top view)

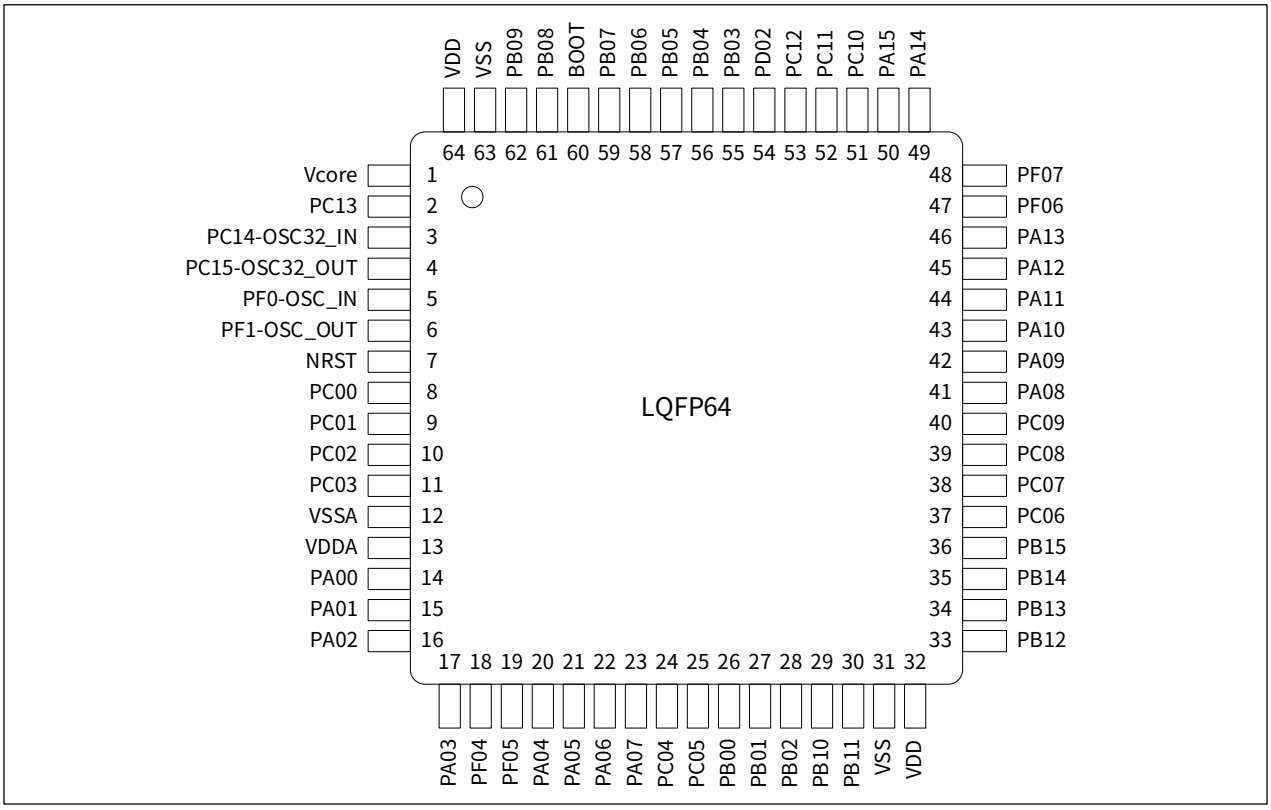


Table 5-1 Legend/abbreviations used in the pinout table

Name	Abbreviation	Definition
Pin name	Unless otherwise specified in brackets below the pin name, the pin function after reset is the same as the actual pin name	
Pin type	S	Supply pin
	I	Input only pin
	I/O	Input / output pin
I/O structure	TTa	Connect the I/O port for the analog function
	TC	Standard I/ O pin
	B	Dedicated BOOT pin
	RST	Reset input pin
Notes	Unless otherwise specified by a note, all pins are set as high impedance input state after reset	
Additional functions	Digital function	Functions selected through GPIOx_AFRy registers
	Analog function	Functions directly selected through peripheral registers

Table 5-2 CW32L083 pin definitions

Pin number			Pin name (function after reset)	Pin type	I/O structure	Notes	Additional functions	
LQFP100	LQFP80	LQFP64					Digital function	Analog function
1	-	-	PE02	I/O	TTa	-	LPTIM_ETR, LVD_OUT, IR_OUT, GTIM1_ETR, ATIM_BK	SEG49
2	-	-	PE03	I/O	TTa	-	LPTIM_CH1, UART5_RXD, I2C2_SCL, SPI1_CS, GTIM1_CH4, ATIM_CH1B	SEG48
3	-	-	PE04	I/O	TC	-	LPTIM_CH2, UART5_TXD, I2C2_SDA, SPI1_SCK, GTIM1_CH3, ATIM_CH2B	
4	-	-	PE05	I/O	TC	-	UART5_CTS, UART6_RXD，SPI1_MISO, GTIM1_CH2，ATIM_CH3B	
5	-	-	PE06	I/O	TC	-	UART5_RTS, UART6_TXD, SPI1_MOSI, GTIM1_CH1, ATIM_ETR	
6	1	1	Vcore	-	-	-	Vcore is the regulator supply output and must be connected to a 1μF capacitor to ground and is for internal circuit use only.	
7	2	2	PC13	I/O	TC	-	PLL_OUT, RTC_1Hz, UART1_CTS, RTC_OUT, BTIM_ETR, GTIM3_ETR, RTC_TAMP	
8	3	3	PC14	I/O	TC	-	AUTOTRIM_ETR, GTIM4_CH4, UART1_RTS, UART4_TXD, SPI2_MISO, GTIM3_TOGP, GTIM3_CH1	OSC32_IN
9	4	4	PC15	I/O	TC	-	HSE_OUT, GTIM4_CH3, GTIM4_ETR, UART4_RXD, SPI2_MOSI, GTIM3_TOGN, GTIM3_CH2	OSC32_ OUT
10	5	-	PF09	I/O	TC	-	UART2_TXD, UART3_RXD, BTIM3_TOGP, RTC_OUT, GTIM1_CH1, HCLK_OUT	
11	6	-	PF10	I/O	TC	-	UART2_RXD, UART3_TXD, BTIM3_TOGN, HSIOSC_OUT, GTIM1_CH2, MCO_OUT	
12	7	5	PF00	I/O	TC	-	AUTOTRIM_ETR, GTIM4_CH2, I2C1_SDA, BTIM1_TOGN, SPI2_SCK, GTIM2_TOGP, GTIM3_CH3	OSC_IN
13	8	6	PF01	I/O	TC	-	LSE_OUT, GTIM4_CH1, I2C1_SCL, BTIM1_TOGP, SPI2_CS, GTIM2_TOGN, GTIM3_CH4	OSC_OUT
14	9	7	NRST	I	RST	-	Device reset input	

Pin number			Pin name (function after reset)	Pin type	I/O structure	Notes	Additional functions	
LQFP100	LQFP80	LQFP64					Digital function	Analog function
15	10	8	PC00	I/O	TTa	-	UART4_CTS, GTIM2_CH4, SPI1_CS, LPTIM_CH1, UART5_RXD, ATIM_CH1A, I2C2_SCL	SEG23
16	11	9	PC01	I/O	TTa	-	UART4_RTS, GTIM2_CH3, SPI1_SCK, LPTIM_OUT, UART5_TXD, ATIM_CH2A, I2C2_SDA	SEG22
17	12	10	PC02	I/O	TTa	-	UART4_RXD, GTIM2_CH2, SPI1_MISO, LPTIM_CH2, UART1_TXD, ATIM_CH3A	SEG21
18	13	11	PC03	I/O	TTa	-	UART4_TXD, GTIM2_CH1, SPI1_MOSI, LPTIM_ETR, UART1_RXD, ATIM_BK	SEG20
19	14	-	PF02	I/O	TC	-	UART5_CTS, LVD_OUT, LSI_OUT, GTIM3_TOGP, MCO_OUT	
20	15	12	VSSA	S	-	-	Analog ground	
21	16	13	VDDA	S	-	-	Analog power supply	
22	17	-	PF08	I/O	TC	-	UART5_RTS, PLL_OUT, PCLK_OUT, GTIM3_TOGN	
23	18	14	PA00	I/O	TTa	-	UART3_CTS, UART6_CTS, RTC_TAMP, VC1_OUT, SPI2_MISO, GTIM2_CH1, GTIM2_ETR	ADC_AIN0, VC1_CH0, LVD_CH1
24	19	15	PA01	I/O	TTa	-	UART3_RTS, UART6_RTS, I2C2_SCL, LVD_OUT, SPI2_MOSI, GTIM2_CH2, RTC_TAMP	ADC_AIN1, VC1_CH1, SEG19
25	20	16	PA02	I/O	TTa	-	UART3_TXD, UART6_TXD, I2C2_SDA, VC2_OUT, SPI2_SCK, GTIM2_CH3, AUTOTRIM_ETR	ADC_AIN2, VC1_CH2, SEG18
26	21	17	PA03	I/O	TTa	-	UART3_RXD, UART6_RXD, GTIM2_CH2, PCLK_OUT, SPI2_CS, GTIM2_CH4, ATIM_CH3A	ADC_AIN3, VC1_CH3, SEG17
-	22	18	PF04	I/O	TC	-	UART1_TXD, GTIM4_CH2, UART5_RXD	
27	-	-	VSS	S	-	-	Digital ground	
-	23	19	PF05	I/O	TC	-	UART1_RXD, BTIM_ETR, UART5_TXD, AUTOTRIM_ETR	
28	-	-	VDD	S	-	-	Digital power supply	

Pin number			Pin name (function after reset)	Pin type	I/O structure	Notes	Additional functions	
LQFP100	LQFP80	LQFP64					Digital function	Analog function
29	24	20	PA04	I/O	TTa	-	UART4_TXD, UART2_CTS, I2C2_SCL, HCLK_OUT, SPI1_CS, GTIM2_ETR, ATIM_CH2A	ADC_AIN4, VC1_CH4
30	25	21	PA05	I/O	TTa	-	GTIM2_ETR, UART2_RTS, I2C2_SDA, BTIM2_TOGN, SPI1_SCK, GTIM2_CH1, ATIM_CH1A	ADC_AIN5, VC1_CH5
31	26	22	PA06	I/O	TTa	-	GTIM3_CH1, UART2_TXD, VC1_OUT, BTIM2_TOGP, SPI1_MISO, GTIM1_CH1, ATIM_BK	ADC_AIN6, VC1_CH6, SEG16
32	27	23	PA07	I/O	TTa	-	GTIM4_CH1, UART2_RXD, VC2_OUT, BTIM1_TOGN, SPI1_MOSI, GTIM1_CH2, ATIM_CH1B	ADC_AIN7, VC1_CH7, SEG15
33	28	24	PC04	I/O	TTa	-	UART1_TXD, UART6_RXD, IR_OUT, LSI_OUT	ADC_AIN8, SEG14
34	29	25	PC05	I/O	TTa	-	UART1_RXD, UART6_TXD, MCO_OUT, LPTIM_ETR, LPTIM_OUT	ADC_AIN9, SEG13
35	30	26	PB00	I/O	TTa	-	UART5_RXD, UART1_CTS, I2C2_SCL, BTIM1_TOGP, HSIOSC_OUT, GTIM1_CH3, ATIM_CH2B	ADC_AIN10/ ExRef, VC2_CH0, LVD_CH2, SEG12
36	31	27	PB01	I/O	TTa	-	UART5_TXD, UART1_RTS, I2C2_SDA, GTIM4_TOGP, BTIM3_TOGN, GTIM1_CH4, ATIM_CH3B	ADC_AIN11, VC2_CH1, SEG11
37	32	28	PB02	I/O	TTa	-	UART2_CTS, UART1_TXD, LPTIM_OUT, GTIM4_TOGN, BTIM3_TOGP, GTIM1_ ETR, ATIM_CH1A	ADC_ AIN12, VC2_CH2
38	-	-	PE07	I/O	TTa	-	UART2_RTS, LPTIM_CH1, GTIM1_CH4, GTIM4_ETR, BTIM_ETR, ATIM_CH2A	SEG47
39	-	-	PE08	I/O	TTa	-	UART1_TXD, LPTIM_CH2, GTIM1_CH3, SPI1_CS, GTIM4_CH1, ATIM_CH3A	SEG46
40	-	-	PE09	I/O	TTa	-	UART1_RXD, LPTIM_OUT, GTIM1_ETR, SPI1_SCK, GTIM3_CH1, ATIM_BK	SEG45
41	-	-	PE10	I/O	TTa	-	UART4_TXD, LPTIM_ETR, GTIM1_CH2, SPI1_MISO, GTIM3_CH2, ATIM_ETR	SEG44
42	-	-	PE11	I/O	TC	-	UART4_RXD, UART1_RXD, GTIM1_CH1, SPI1_MOSI, GTIM3_CH3	

Pin number			Pin name (function after reset)	Pin type	I/O structure	Notes	Additional functions	
LQFP100	LQFP80	LQFP64					Digital function	Analog function
43	33	-	PE12	I/O	TTa	-	UART3_TXD, GTIM2_CH4, SPI2_CS, GTIM3_CH4, ATIM_CH1B	SEG43
44	34	-	PE13	I/O	TTa	-	UART3_RXD, GTIM2_CH3, SPI2_SCK, GTIM4_CH2, ATIM_CH2B	SEG42
45	35	-	PE14	I/O	TTa	-	UART2_TXD, GTIM2_CH2, SPI2_MISO, GTIM4_CH3, ATIM_CH3B	SEG41
46	36	-	PE15	I/O	TTa	-	UART2_RXD, GTIM2_CH1, SPI2_MOSI, GTIM4_CH4, ATIM_BK	SEG40
47	37	29	PB10	I/O	TTa	-	UART2_RTS, UART4_RXD, I2C1_SCL, I2C2_SCL, SPI2_SCK, GTIM2_CH3, ATIM_CH2A	VC2_CH3, SEG10
48	38	30	PB11	I/O	TTa	-	GTIM4_ETR, UART4_TXD, I2C1_SDA, I2C2_SDA, BTIM_ETR, GTIM2_CH4, ATIM_CH3A	LVD_CH3, SEG9
49	39	31	VSS	S	-	-	Digital ground	
50	40	32	VDD	S	-	-	Digital power supply	
51	41	33	PB12	I/O	TTa	-	GTIM2_TOGP, GTIM4_CH4, LSE_OUT, SPI2_CS, SPI1_CS, GTIM1_TOGP, ATIM_BK	SEG8
52	42	34	PB13	I/O	TTa	-	GTIM2_TOGN, GTIM4_CH3, I2C2_SCL, SPI2_SCK, SPI1_SCK, GTIM1_TOGN, ATIM_CH1B	SEG7
53	43	35	PB14	I/O	TTa	-	GTIM2_CH1, GTIM4_CH2, I2C2_SDA, SPI2_MISO, SPI1_MISO, RTC_OUT, ATIM_CH2B	SEG6
54	44	36	PB15	I/O	TTa	-	GTIM2_CH2, GTIM4_CH1, BTIM2_TOGN, SPI2_MOSI, SPI1_MOSI, RTC_1Hz, ATIM_CH3B	SEG5
55	45	-	PD08	I/O	TTa	-	GTIM2_CH3, LPTIM_OUT, UART1_TXD, SPI2_CS, GTIM1_CH1, ATIM_CH1A	SEG39
56	46	-	PD09	I/O	TTa	-	GTIM2_CH4, LPTIM_CH2, UART1_RXD, SPI2_SCK, GTIM1_CH2, ATIM_CH2A	SEG38
57	47	-	PD10	I/O	TTa	-	UART5_TXD, LPTIM_CH1, GTIM4_CH1, SPI2_MISO, GTIM1_CH3, ATIM_CH3A	SEG37
58	48	-	PD11	I/O	TTa	-	UART5_RXD, LPTIM_ETR, GTIM4_CH2, SPI2_MOSI, GTIM1_CH4, ATIM_BK	SEG36

Pin number			Pin name (function after reset)	Pin type	I/O structure	Notes	Additional functions	
LQFP100	LQFP80	LQFP64					Digital function	Analog function
59	-	-	PD12	I/O	TTa	-	UART5_CTS, UART4_RXD, GTIM4_CH3, SPI1_CS, BTIM3_TOGP, AUTOTRIM_ETR	SEG35
60	-	-	PD13	I/O	TTa	-	UART5_RTS, UART4_TXD, GTIM4_CH4, SPI1_SCK, BTIM3_TOGN	SEG34
61	-	-	PD14	I/O	TTa	-	UART2_TXD, HCLK_OUT, GTIM2_ETR, SPI1_MISO	SEG33
62	-	-	PD15	I/O	TTa	-	UART2_RXD, PCLK_OUT, BTIM_ETR, SPI1_MOSI	SEG32
63	49	37	PC06	I/O	TTa	-	UART4_RXD, UART3_TXD, BTIM2_TOGP, GTIM2_CH4, ATIM_CH1B	SEG4
64	50	38	PC07	I/O	TTa	-	UART4_TXD, UART3_RXD, BTIM2_TOGN, GTIM2_CH3, ATIM_CH2B	SEG3
65	51	39	PC08	I/O	TTa	-	UART4_CTS, UART6_TXD, GTIM4_ETR, GTIM2_CH2, ATIM_CH3B	SEG2
66	52	40	PC09	I/O	TTa	-	UART4_RTS, UART6_RXD, I2C1_SDA, GTIM2_CH1, ATIM_ETR	SEG1
67	53	41	PA08	I/O	TTa	-	LPTIM_ETR, UART1_TXD, BTIM2_TOGP, MCO_OUT, LVD_OUT, GTIM3_ETR, ATIM_CH1A	VC2_CH4, SEG0
68	54	42	PA09	I/O	TTa	-	UART3_TXD, UART1_RXD, I2C1_SCL, BTIM1_TOGN, SPI1_CS, GTIM3_CH1, ATIM_CH2A	VC2_CH5, COM0
69	55	43	PA10	I/O	TTa	-	UART3_RXD, UART1_CTS, I2C1_SDA, BTIM1_TOGP, SPI1_SCK, GTIM3_CH2, ATIM_CH3A	VC2_CH6, COM1
70	56	44	PA11	I/O	TTa	-	UART3_CTS, UART1_RTS, I2C2_SCL, VC1_OUT, SPI1_MISO, GTIM3_CH3	VC2_CH7, COM2
71	57	45	PA12	I/O	TTa	-	UART3_RTS, BTIM_ETR, I2C2_SDA, VC2_OUT, SPI1_MOSI, GTIM3_CH4, ATIM_ETR	COM3
72	58	46	PA13/ SWDIO	I/O	TC	1	I2C1_SDA, UART1_RXD, UART2_TXD, I2C2_SCL, IR_OUT	
73	59	47	PF06	I/O	TC	-	UART6_CTS, I2C1_SCL, GTIM4_TOGP, UART2_CTS, I2C2_SCL, GTIM3_TOGP, BTIM3_TOGN	
74	-	-	VSS	S	-	-	Digital ground	

Pin number			Pin name (function after reset)	Pin type	I/O structure	Notes	Additional functions	
LQFP100	LQFP80	LQFP64					Digital function	Analog function
-	60	48	PF07	I/O	TC	-	UART6_RTS, I2C1_SDA, GTIM4_TOGN, UART2_RTS, I2C2_SDA, GTIM3_TOGN, BTIM3_TOGP	
75	-	-	VDD	S	-	-	Digital power supply	
76	61	49	PA14/ SWCLK	I/O	TC	1	UART3_TXD, I2C1_SCL, UART1_TXD, UART2_RXD, I2C2_SDA	
77	62	50	PA15	I/O	TTa	-	UART3_RXD, GTIM2_CH1, UART1_RXD, UART2_TXD, SPI1_CS, GTIM2_ETR, ATIM_CH1B	SEG55
78	63	51	PC10	I/O	TTa	-	UART4_TXD, GTIM3_CH1, HCLK_OUT, BTIM1_TOGP, VC1_OUT, LPTIM_CH1, ATIM_CH2B	SEG31/ COM4
79	64	52	PC11	I/O	TTa	-	UART4_RXD, GTIM3_CH2, IR_OUT, BTIM1_TOGN, VC2_OUT, LPTIM_CH2, ATIM_CH3B	SEG30/ COM5
80	65	53	PC12	I/O	TTa	-	UART5_TXD, PCLK_OUT, LVD_OUT, UART6_RXD, PLL_OUT, HSIOSC_OUT	SEG29/ COM6
81	66	-	PD00	I/O	TC	-	UART6_RXD, I2C2_SCL, AUTOTRIM_ETR, SPI2_CS, MCO_OUT	
82	67	-	PD01	I/O	TC	-	UART6_TXD, I2C2_SDA, RTC_1Hz, SPI2_SCK, RTC_TAMP	
83	68	54	PD02	I/O	TTa	-	UART5_RXD, GTIM4_CH1, BTIM_ETR, UART6_TXD, RTC_1Hz, GTIM3_ETR, ATIM_ETR	SEG28/ COM7
84	69	-	PD03	I/O	TTa	-	UART6_CTS, I2C2_SCL, VC1_OUT, SPI2_MISO, GTIM1_CH3, ATIM_BK	SEG54
85	70	-	PD04	I/O	TC	-	UART6_RTS, I2C2_SDA, VC2_OUT, SPI2_MOSI, GTIM1_CH4, ATIM_CH3A	
86	-	-	PD05	I/O	TC	-	UART4_TXD, GTIM2_CH1, UART3_TXD, LPTIM_CH1, BTIM2_TOGP, LSI_OUT, ATIM_CH2A	
87	-	-	PD06	I/O	TC	-	I2C1_SCL, GTIM2_CH4, UART3_RXD, LPTIM_CH2, BTIM2_TOGN, GTIM2_TOGP, ATIM_CH1A	

Pin number			Pin name (function after reset)	Pin type	I/O structure	Notes	Additional functions	
LQFP100	LQFP80	LQFP64					Digital function	Analog function
88	-	-	PD07	I/O	TC	-	I2C1_SDA, GTIM2_CH3, MCO_OUT, UART2_RXD, SPI1_CS, GTIM2_TOGN, ATIM_CH1B	
89	71	55	PB03	I/O	TTa	-	UART3_RTS, GTIM2_CH2, UART4_CTS, UART2_TXD, SPI1_SCK, GTIM1_ETR, ATIM_CH2B	SEG27/ VLCD4
90	72	56	PB04	I/O	TTa	-	UART3_CTS, GTIM4_ETR, UART4_RTS, UART2_RXD, SPI1_MISO, GTIM1_CH1, ATIM_CH3B	SEG26/ VLCD3
91	73	57	PB05	I/O	TTa	-	UART4_RXD, GTIM3_CH4, LPTIM_CH1, UART2_RTS, SPI1_MOSI, GTIM1_CH2, ATIM_CH1A	SEG25/ VLCD2
92	74	58	PB06	I/O	TTa	-	UART6_TXD, GTIM3_CH3, LPTIM_ETR, I2C1_SCL, SPI2_MOSI, GTIM1_TOGP, ATIM_CH2A	SEG24/ VLCD1
93	75	59	PB07	I/O	TTa	-	UART6_RXD, GTIM3_CH2, LPTIM_CH2, I2C1_SDA, SPI2_MISO, GTIM1_TOGN, ATIM_CH3A	
94	76	60	PF03/ BOOT	I	B	-		
95	77	61	PB08	I/O	TTa	-	I2C1_SCL, GTIM3_CH1, UART5_TXD, GTIM4_CH2, SPI2_SCK, GTIM1_CH3, ATIM_ETR	SEG53
96	78	62	PB09	I/O	TTa	-	I2C1_SDA, GTIM4_CH1, UART5_RXD, IR_OUT, SPI2_CS, GTIM1_CH4, ATIM_BK	SEG52
97	-	-	PE00	I/O	TTa	-	I2C2_SCL, GTIM4_CH2, LPTIM_ETR, PCLK_OUT, GTIM2_TOGP, GTIM1_CH1, GTIM4_TOGP	SEG51
98	-	-	PE01	I/O	TTa	-	I2C2_SDA, GTIM4_CH3, LPTIM_OUT, HCLK_OUT, GTIM2_TOGN, GTIM1_CH2, GTIM4_TOGN	SEG50
99	79	63	VSS	S	-	-	Digital ground	
100	80	64	VDD	S	-	-	Digital power supply	

Caution 1: Afeter reset，these pins are configured as SWDIO and SWCLK functions，and the internal pull-up resistors are turned on by default.

Table 5-3 Alternate functions selected through GPIOA_AFRy registers for port A

Pin name	AF1	AF2	AF3	AF4	AF5	AF6	AF7
PA00	UART3_CTS	UART6_CTS	RTC_TAMP	VC1_OUT	SPI2_MISO	GTIM2_CH1	GTIM2_ETR
PA01	UART3_RTS	UART6_RTS	I2C2_SCL	LVD_OUT	SPI2_MOSI	GTIM2_CH2	RTC_TAMP
PA02	UART3_TXD	UART6_TXD	I2C2_SDA	VC2_OUT	SPI2_SCK	GTIM2_CH3	AUTOTRIM_ETR
PA03	UART3_RXD	UART6_RXD	GTIM2_CH2	PCLK_OUT	SPI2_CS	GTIM2_CH4	ATIM_CH3A
PA04	UART4_TXD	UART2_CTS	I2C2_SCL	HCLK_OUT	SPI1_CS	GTIM2_ETR	ATIM_CH2A
PA05	GTIM2_ETR	UART2_RTS	I2C2_SDA	BTIM2_TOGN	SPI1_SCK	GTIM2_CH1	ATIM_CH1A
PA06	GTIM3_CH1	UART2_TXD	VC1_OUT	BTIM2_TOGP	SPI1_MISO	GTIM1_CH1	ATIM_BK
PA07	GTIM4_CH1	UART2_RXD	VC2_OUT	BTIM1_TOGN	SPI1_MOSI	GTIM1_CH2	ATIM_CH1B
PA08	LPTIM_ETR	UART1_TXD	BTIM2_TOGP	MCO_OUT	LVD_OUT	GTIM3_ETR	ATIM_CH1A
PA09	UART3_TXD	UART1_RXD	I2C1_SCL	BTIM1_TOGN	SPI1_CS	GTIM3_CH1	ATIM_CH2A
PA10	UART3_RXD	UART1_CTS	I2C1_SDA	BTIM1_TOGP	SPI1_SCK	GTIM3_CH2	ATIM_CH3A
PA11	UART3_CTS	UART1_RTS	I2C2_SCL	VC1_OUT	SPI1_MISO	GTIM3_CH3	
PA12	UART3_RTS	BTIM_ETR	I2C2_SDA	VC2_OUT	SPI1_MOSI	GTIM3_CH4	ATIM_ETR
PA13/ SWDIO		I2C1_SDA	UART1_RXD	UART2_TXD	I2C2_SCL	IR_OUT	
PA14/ SWCLK	UART3_TXD	I2C1_SCL	UART1_TXD	UART2_RXD	I2C2_SDA		
PA15	UART3_RXD	GTIM2_CH1	UART1_RXD	UART2_TXD	SPI1_CS	GTIM2_ETR	ATIM_CH1B

Table 5-4 Alternate functions selected through GPIOB_AFRy registers for port B

Pin name	AF1	AF2	AF3	AF4	AF5	AF6	AF7
PB00	UART5_RXD	UART1_CTS	I2C2_SCL	BTIM1_TOGP	HSI_OUT	GTIM1_CH3	ATIM_CH2B
PB01	UART5_TXD	UART1_RTS	I2C2_SDA	GTIM4_TOGP	BTIM3_TOGN	GTIM1_CH4	ATIM_CH3B
PB02	UART2_CTS	UART1_TXD	LPTIM_OUT	GTIM4_TOGN	BTIM3_TOGP	GTIM1_ETR	ATIM_CH1A
PB03	UART3_RTS	GTIM2_CH2	UART4_CTS	UART2_TXD	SPI1_SCK	GTIM1_ETR	ATIM_CH2B
PB04	UART3_CTS	GTIM4_ETR	UART4_RTS	UART2_RXD	SPI1_MISO	GTIM1_CH1	ATIM_CH3B
PB05	UART4_RXD	GTIM3_CH4	LPTIM_CH1	UART2_RTS	SPI1_MOSI	GTIM1_CH2	ATIM_CH1A
PB06	UART6_TXD	GTIM3_CH3	LPTIM_ETR	I2C1_SCL	SPI2_MOSI	GTIM1_TOGP	ATIM_CH2A
PB07	UART6_RXD	GTIM3_CH2	LPTIM_CH2	I2C1_SDA	SPI2_MISO	GTIM1_TOGN	ATIM_CH3A
PB08	I2C1_SCL	GTIM3_CH1	UART5_TXD	GTIM4_CH2	SPI2_SCK	GTIM1_CH3	ATIM_ETR
PB09	I2C1_SDA	GTIM4_CH1	UART5_RXD	IR_OUT	SPI2_CS	GTIM1_CH4	ATIM_BK
PB10	UART2_RTS	UART4_RXD	I2C1_SCL	I2C2_SCL	SPI2_SCK	GTIM2_CH3	ATIM_CH2A
PB11	GTIM4_ETR	UART4_TXD	I2C1_SDA	I2C2_SDA	BTIM_ETR	GTIM2_CH4	ATIM_CH3A
PB12	GTIM2_TOGP	GTIM4_CH4	LSE_OUT	SPI2_CS	SPI1_CS	GTIM1_TOGP	ATIM_BK
PB13	GTIM2_TOGN	GTIM4_CH3	I2C2_SCL	SPI2_SCK	SPI1_SCK	GTIM1_TOGN	ATIM_CH1B
PB14	GTIM2_CH1	GTIM4_CH2	I2C2_SDA	SPI2_MISO	SPI1_MISO	RTC_OUT	ATIM_CH2B
PB15	GTIM2_CH2	GTIM4_CH1	BTIM2_TOGN	SPI2_MOSI	SPI1_MOSI	RTC_1Hz	ATIM_CH3B

Table 5-5 Alternate functions selected through GPIOC_AFRy registers for port C

Pin name	AF1	AF2	AF3	AF4	AF5	AF6	AF7
PC00	UART4_CTS	GTIM2_CH4	SPI1_CS	LPTIM_CH1	UART5_RXD	ATIM_CH1A	I2C2_SCL
PC01	UART4_RTS	GTIM2_CH3	SPI1_SCK	LPTIM_OUT	UART5_TXD	ATIM_CH2A	I2C2_SDA
PC02	UART4_RXD	GTIM2_CH2	SPI1_MISO	LPTIM_CH2	UART1_TXD	ATIM_CH3A	
PC03	UART4_TXD	GTIM2_CH1	SPI1_MOSI	LPTIM_ETR	UART1_RXD	ATIM_BK	
PC04	UART1_TXD	UART6_RXD	IR_OUT			LSI_OUT	
PC05	UART1_RXD	UART6_TXD	MCO	LPTIM_ETR	LPTIM_OUT		
PC06	UART4_RXD	UART3_TXD	BTIM2_TOGP		GTIM2_CH4	ATIM_CH1B	
PC07	UART4_TXD	UART3_RXD	BTIM2_TOGN		GTIM2_CH3	ATIM_CH2B	
PC08	UART4_CTS	UART6_TXD	GTIM4_ETR		GTIM2_CH2	ATIM_CH3B	
PC09	UART4_RTS	UART6_RXD	I2C1_SDA		GTIM2_CH1	ATIM_ETR	
PC10	UART4_TXD	GTIM3_CH1	HCLK_OUT	BTIM1_TOGP	VC1_OUT	LPTIM_CH1	ATIM_CH2B
PC11	UART4_RXD	GTIM3_CH2	IR_OUT	BTIM1_TOGN	VC2_OUT	LPTIM_CH2	ATIM_CH3B
PC12	UART5_TXD	PCLK_OUT	LVD_OUT	UART6_RXD	PLL_OUT	HSI_OUT	
PC13	PLL_OUT	RTC_1Hz	UART1_CTS	RTC_OUT	BTIM_ETR	GTIM3_ETR	RTC_TAMP
PC14	AUTOTRIM_ETR	GTIM4_CH4	UART1_RTS	UART4_TXD	SPI2_MISO	GTIM3_TOGP	GTIM3_CH1
PC15	HSE_OUT	GTIM4_CH3	GTIM4_ETR	UART4_RXD	SPI2_MOSI	GTIM3_TOGN	GTIM3_CH2

Table 5-6 Alternate functions selected through GPIOD_AFRy registers for port D

Pin name	AF1	AF2	AF3	AF4	AF5	AF6	AF7
PD00	UART6_RXD		I2C2_SCL	AUTOTRIM_ETR	SPI2_CS	MCO_OUT	
PD01	UART6_TXD		I2C2_SDA	RTC_1Hz	SPI2_SCK	RTC_TAMP	
PD02	UART5_RXD	GTIM4_CH1	BTIM_ETR	UART6_TXD	RTC_1Hz	GTIM3_ETR	ATIM_ETR
PD03	UART6_CTS		I2C2_SCL	VC1_OUT	SPI2_MISO	GTIM1_CH3	ATIM_BK
PD04	UART6_RTS		I2C2_SDA	VC2_OUT	SPI2_MOSI	GTIM1_CH4	ATIM_CH3A
PD05	UART4_TXD	GTIM2_CH1	UART3_TXD	LPTIM_CH1	BTIM2_TOGP	LSI_OUT	ATIM_CH2A
PD06	I2C1_SCL	GTIM2_CH4	UART3_RXD	LPTIM_CH2	BTIM2_TOGN	GTIM2_TOGP	ATIM_CH1A
PD07	I2C1_SDA	GTIM2_CH3	MCO_OUT	UART2_RXD	SPI1_CS	GTIM2_TOGN	ATIM_CH1B
PD08	GTIM2_CH3	LPTIM_OUT	UART1_TXD	SPI2_CS	GTIM1_CH1	ATIM_CH1A	
PD09	GTIM2_CH4	LPTIM_CH2	UART1_RXD	SPI2_SCK	GTIM1_CH2	ATIM_CH2A	
PD10	UART5_TXD	LPTIM_CH1	GTIM4_CH1	SPI2_MISO	GTIM1_CH3	ATIM_CH3A	
PD11	UART5_RXD	LPTIM_ETR	GTIM4_CH2	SPI2_MOSI	GTIM1_CH4	ATIM_BK	
PD12	UART5_CTS	UART4_RXD	GTIM4_CH3	SPI1_CS	BTIM3_TOGP	AUTOTRIM_ETR	
PD13	UART5_RTS	UART4_TXD	GTIM4_CH4	SPI1_SCK	BTIM3_TOGN		
PD14	UART2_TXD	HCLK_OUT	GTIM2_ETR	SPI1_MISO			
PD15	UART2_RXD	PCLK_OUT	BTIM_ETR	SPI1_MOSI			

Table 5-7 Alternate functions selected through GPIOE_AFRy registers for port E

Pin name	AF1	AF2	AF3	AF4	AF5	AF6	AF7
PE00	I2C2_SCL	GTIM4_CH2	LPTIM_ETR	PCLK_OUT	GTIM2_TOGP	GTIM1_CH1	GTIM4_TOGP
PE01	I2C2_SDA	GTIM4_CH3	LPTIM_OUT	HCLK_OUT	GTIM2_TOGN	GTIM1_CH2	GTIM4_TOGN
PE02	LPTIM_ETR		LVD_OUT	IR_OUT	GTIM1_ETR	ATIM_BK	
PE03	LPTIM_CH1	UART5_RXD	I2C2_SCL	SPI1_CS	GTIM1_CH4	ATIM_CH1B	
PE04	LPTIM_CH2	UART5_TXD	I2C2_SDA	SPI1_SCK	GTIM1_CH3	ATIM_CH2B	
PE05		UART5_CTS	UART6_RXD	SPI1_MISO	GTIM1_CH2	ATIM_CH3B	
PE06		UART5_RTS	UART6_TXD	SPI1_MOSI	GTIM1_CH1	ATIM_ETR	
PE07	UART2_RTS	LPTIM_CH1	GTIM1_CH4	GTIM4_ETR	BTIM_ETR	ATIM_CH2A	
PE08	UART1_TXD	LPTIM_CH2	GTIM1_CH3	SPI1_CS	GTIM4_CH1	ATIM_CH3A	
PE09	UART1_RXD	LPTIM_OUT	GTIM1_ETR	SPI1_SCK	GTIM3_CH1	ATIM_BK	
PE10	UART4_TXD	LPTIM_ETR	GTIM1_CH2	SPI1_MISO	GTIM3_CH2	ATIM_ETR	
PE11	UART4_RXD	UART1_RXD	GTIM1_CH1	SPI1_MOSI	GTIM3_CH3		
PE12	UART3_TXD		GTIM2_CH4	SPI2_CS	GTIM3_CH4	ATIM_CH1B	
PE13	UART3_RXD		GTIM2_CH3	SPI2_SCK	GTIM4_CH2	ATIM_CH2B	
PE14	UART2_TXD		GTIM2_CH2	SPI2_MISO	GTIM4_CH3	ATIM_CH3B	
PE15	UART2_RXD		GTIM2_CH1	SPI2_MOSI	GTIM4_CH4	ATIM_BK	

Table 5-8 Alternate functions selected through GPIOF_AFRy registers for port F

Pin name	AF1	AF2	AF3	AF4	AF5	AF6	AF7
PF00	AUTOTRIM_ETR	GTIM4_CH2	I2C1_SDA	BTIM1_TOGN	SPI2_SCK	GTIM2_TOGP	GTIM3_CH3
PF01	LSE_OUT	GTIM4_CH1	I2C1_SCL	BTIM1_TOGP	SPI2_CS	GTIM2_TOGN	GTIM3_CH4
PF02	UART5_CTS		LVD_OUT	LSI_OUT	GTIM3_TOGP	MCO_OUT	
PF04	UART1_TXD	GTIM4_CH2		UART5_RXD			
PF05	UART1_RXD	BTIM_ETR		UART5_TXD	AUTOTRIM_ETR		
PF06	UART6_CTS	I2C1_SCL	GTIM4_TOGP	UART2_CTS	I2C2_SCL	GTIM3_TOGP	BTIM3_TOGN
PF07	UART6_RTS	I2C1_SDA	GTIM4_TOGN	UART2_RTS	I2C2_SDA	GTIM3_TOGN	BTIM3_TOGP
PF08	UART5_RTS		PLL_OUT	PCLK_OUT	GTIM3_TOGN		
PF09	UART2_TXD	UART3_RXD		BTIM3_TOGP	RTC_OUT	GTIM1_CH1	HCLK_OUT
PF10	UART2_RXD	UART3_TXD		BTIM3_TOGN	HSI_OUT	GTIM1_CH2	MCO_OUT

6 Address mapping

Figure 6-1 CW32L083 internal address mapping

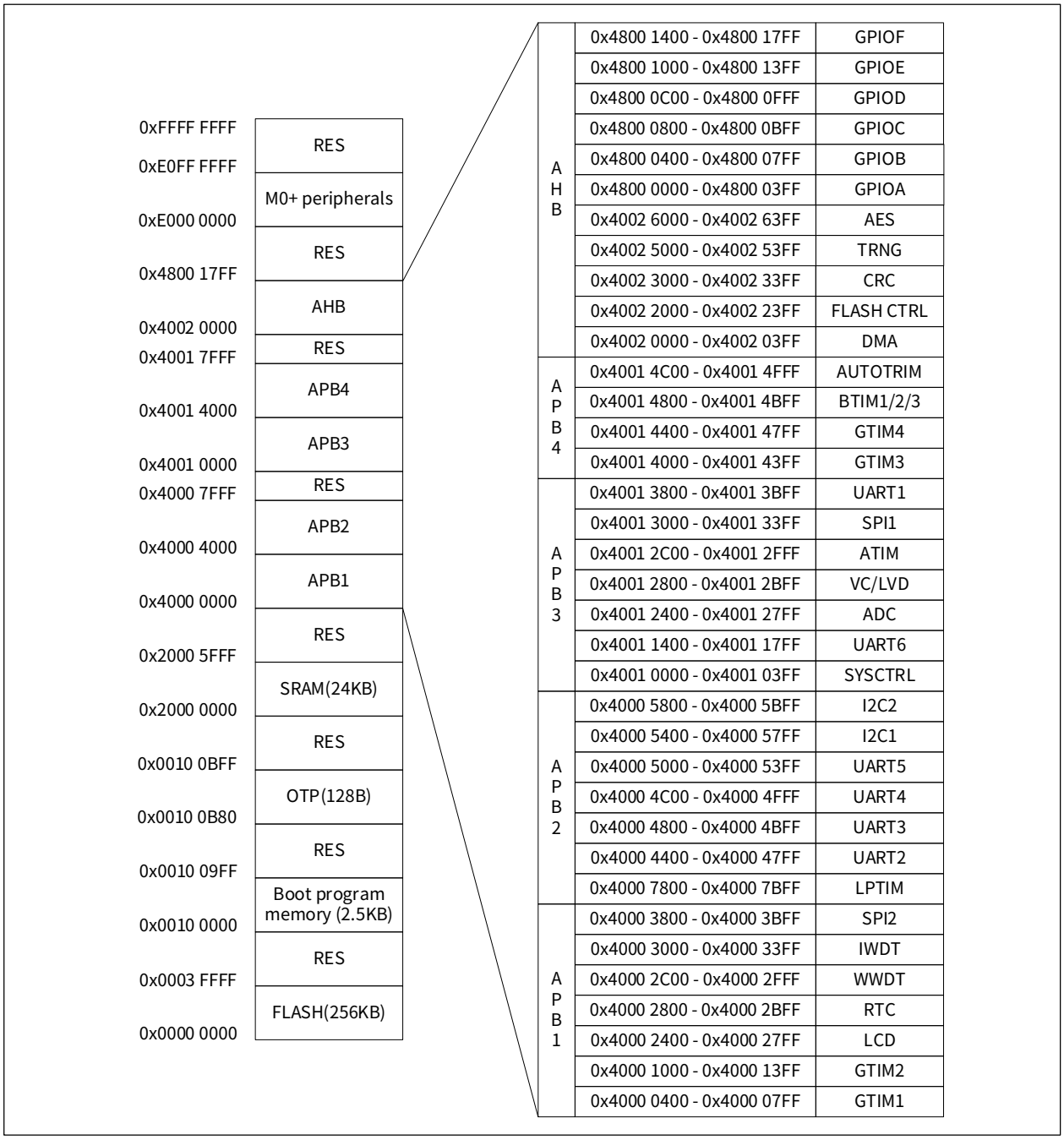


Table 6-1 CW32L083 peripheral register boundary addresses

Device or bus	Boundary address	Size	Peripheral
Main FLASH memory	0x0000 0000 - 0x0003 FFFF	256KB	Main FLASH
OTP memory	0x0010 0B80 - 0x0010 0BFF	128B	OTP
Boot program memory	0x0010 0000 - 0x0010 09FF	2.5KB	BootLoader
SRAM memory	0x2000 0000 - 0x2000 5FFF	24KB	SRAM
APB1 peripheral	0x4000 0400 - 0x4000 07FF	1KB	GTIM1
	0x4000 1000 - 0x4000 13FF	1KB	GTIM2
	0x4000 2400 - 0x4000 27FF	1KB	LCD
	0x4000 2800 - 0x4000 2BFF	1KB	RTC
	0x4000 2C00 - 0x4000 2FFF	1KB	WWDT
	0x4000 3000 - 0x4000 33FF	1KB	IWDT
	0x4000 3800 - 0x4000 3BFF	1KB	SPI2
APB2 peripheral	0x4000 2400 - 0x4000 27FF	1KB	LPTIM
	0x4000 4400 - 0x4000 47FF	1KB	UART2
	0x4000 4800 - 0x4000 4BFF	1KB	UART3
	0x4000 4C00 - 0x4000 4FFF	1KB	UART4
	0x4000 5000 - 0x4000 53FF	1KB	UART5
	0x4000 5400 - 0x4000 57FF	1KB	I2C1
	0x4000 5800 - 0x4000 5BFF	1KB	I2C2
APB3 peripheral	0x4001 0000 - 0x4001 03FF	1KB	SYSCTRL
	0x4001 1400 - 0x4001 17FF	1KB	UART6
	0x4001 2400 - 0x4001 27FF	1KB	ADC
	0x4001 2800 - 0x4001 2BFF	1KB	VC/LVD
	0x4001 2C00 - 0x4001 2FFF	1KB	ATIM
	0x4001 3000 - 0x4001 33FF	1KB	SPI1
	0x4001 3800 - 0x4001 3BFF	1KB	UART1
APB4 peripheral	0x4001 4000 - 0x4001 43FF	1KB	GTIM3
	0x4001 4400 - 0x4001 47FF	1KB	GTIM4
	0x4001 4800 - 0x4001 4BFF	1KB	BTIM1/2/3
	0x4001 4C00 - 0x4001 4FFF	1KB	AUTOTRIM

Device or bus	Boundary address	Size	Peripheral
AHB peripheral	0x4002 0000 - 0x4002 03FF	1KB	DMA
	0x4002 2000 - 0x4002 23FF	1KB	FLASH CTRL
	0x4002 3000 - 0x4002 33FF	1KB	CRC
	0x4002 5000 - 0x4002 53FF	1KB	TRNG
	0x4002 6000 - 0x4002 63FF	1KB	AES
	0x4800 0000 - 0x4800 03FF	1KB	GPIOA
	0x4800 0400 - 0x4800 07FF	1KB	GPIOB
	0x4800 0800 - 0x4800 0BFF	1KB	GPIOC
	0x4800 0C00 - 0x4800 0FFF	1KB	GPIOD
	0x4800 1000 - 0x4800 13FF	1KB	GPIOE
	0x4800 1400 - 0x4800 17FF	1KB	GPIOF
M0+ peripheral	0xE000 0000 - 0xE00F FFFF	1MB	M0+ peripheral

7 Electrical characteristics

7.1 Parameter conditions

Unless otherwise specified, all voltages are referenced to V_{SS}.

7.1.1 Minimum and maximum values

Unless otherwise specified, the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at T_A = 25°C and T_A = $T_A$max (given by the selected temperature range).

Data based on characterization results, design simulation and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation (mean ±3Σ).

7.1.2 Typical values

Unless otherwise specified, typical data are based on T_A = 25°C and V_{DD} = 3.3V. They are given only as design guidelines and are not tested.

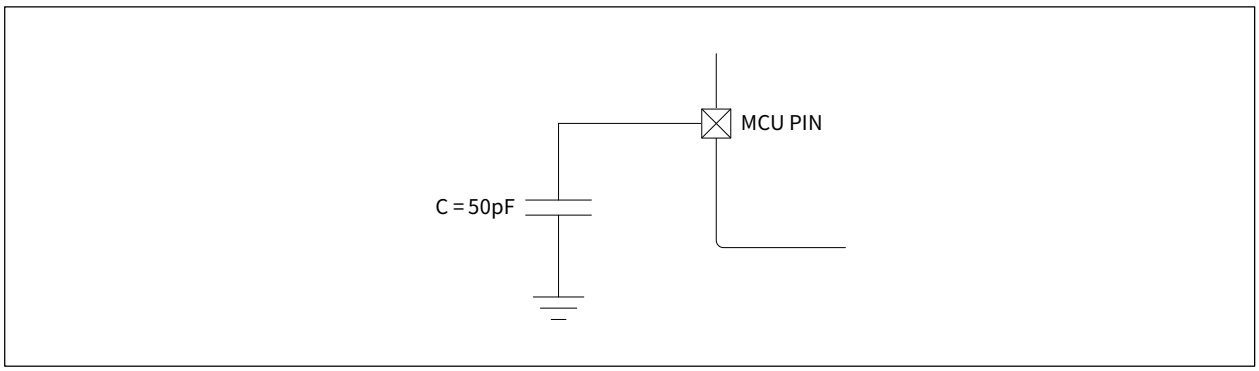
7.1.3 Typical curves

Unless otherwise specified, all typical curves are given only as design guidelines and are not tested.

7.1.4 Loading capacitor

The loading conditions used for pin parameter measurement are shown in the figure below:

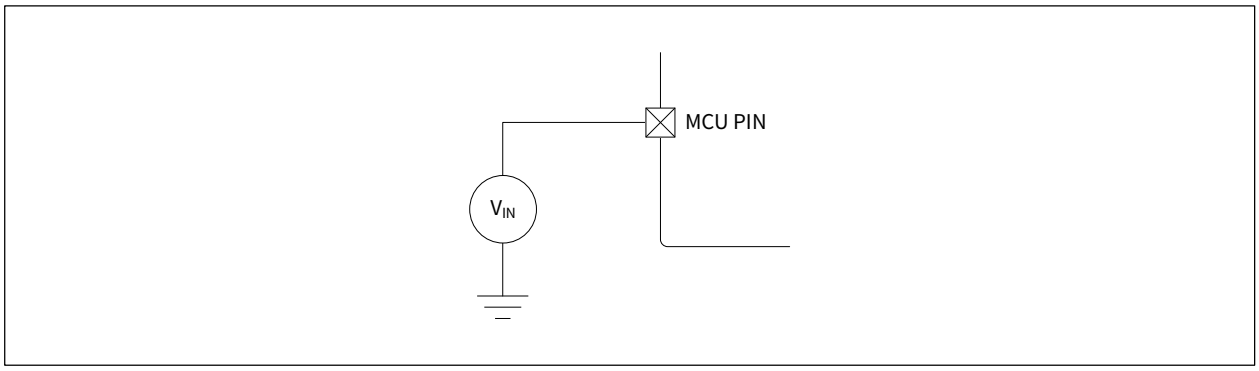
Figure 7-1 Pin loading conditions



7.1.5 Pin input voltage

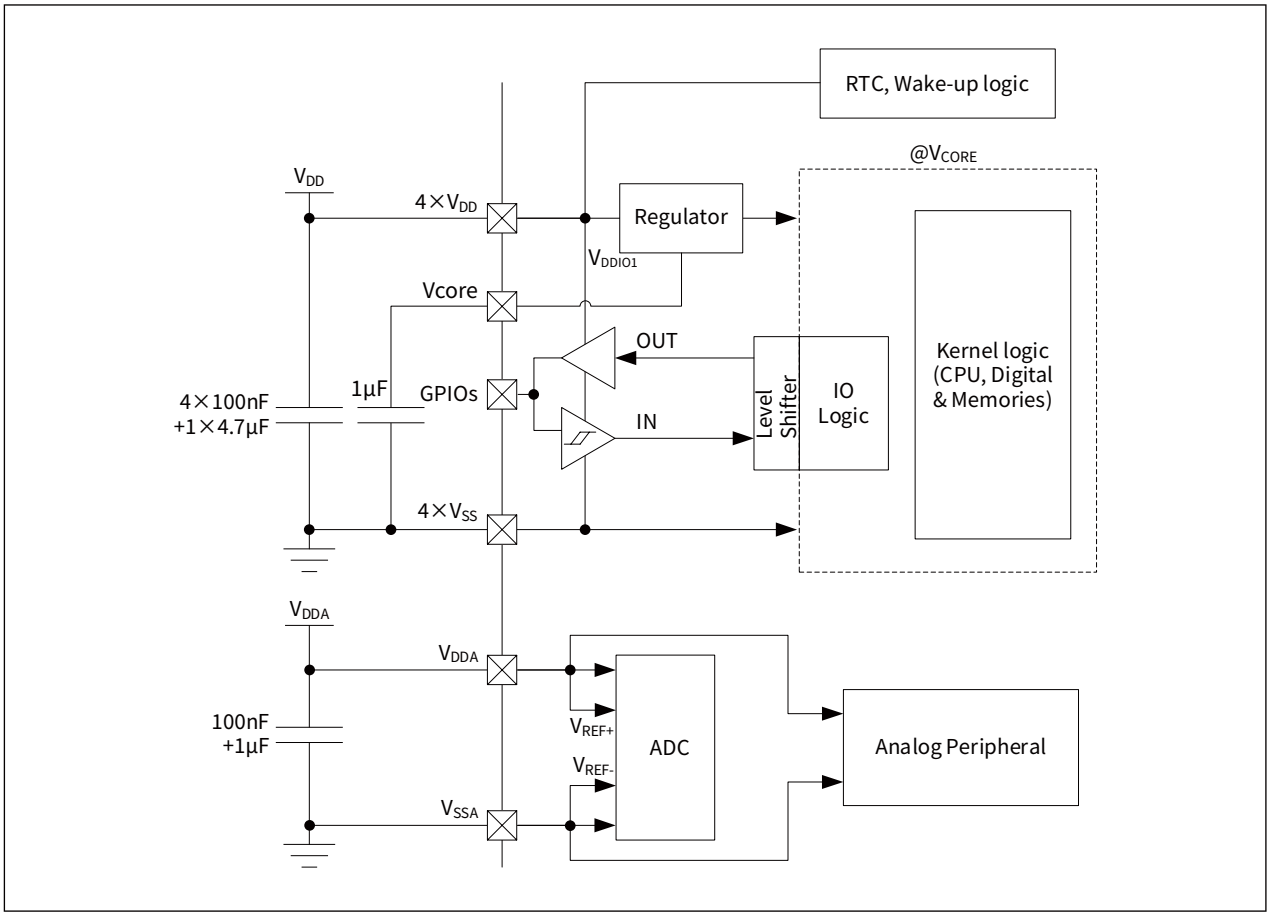
The input voltage measurement on a pin of the device is described in the figure below:

Figure 7-2 Pin input voltage



7.1.6 Power system

Figure 7-3 Power system



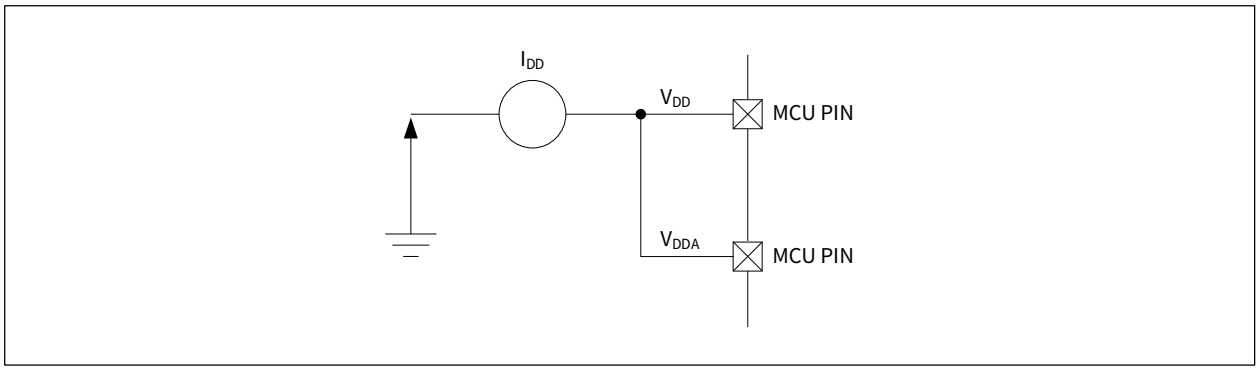
Caution 1: Each power supply pair (V_{DD}/V_{SS}、V_{DDA}/V_{SSA} etc.) must be decoupled with filtering ceramic capacitors as shown above. These capacitors must be placed as close as possible to, or below, the appropriate pins on the underside of the PCB to ensure the good functionality of the device.

Caution 2: All V_{DD} pins must be powered and at the same voltage.

Caution 3: Vcore is the regulator supply output and must be connected to a 1µF capacitor to ground and is for internal circuit use only.

7.1.7 Current consumption measurement

Figure 7-4 Method of measurement



7.2 Absolute maximum ratings

Stresses above the absolute maximum ratings listed in Table 7-1, Table 7-2 and Table 7-3 may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 7-1 Voltage characteristics[1]

Symbol	Ratings	Min.	Max.	Unit
V_{DD} - V_{SS}	External main supply voltage	-0.3	6.0	V
V_{DDA}-V_{SS}	External analog supply voltage	-0.3	6.0	V
V_{DD}-V_{DDA}	Allowed voltage difference for $V_{DD} > V_{DDA}$	-	0.3	V
V_{IN}[2]	Input voltage on port IO	V_{SS} - 0.3	V_{DD} + 0.3	V
$\lvert \Delta V_{DDx} \rvert$	Variations between all the different V_{DD} pins	-	0.05	V
$\lvert V_{SSX}-V_{SS} \rvert$	Variations between all the different V_{SS} pins	-	0.05	V
$V_{ESD(HBM)}$	Electrostatic discharge voltage (human body model)	*See Table 7-24 ESD characteristics*		kV

Caution 1: All main power (V_{DD}, V_{DDA}) and ground (V_{SS}, V_{SSA}) pins must always be connected to the external power supply, in the permitted range.

Caution 2: V_{IN} maximum must always be respected, refer to Table 7-2 for the maximum allowable injection current value.

Table 7-2 Current characteristics

Symbol	Ratings	Max.	Unit
ΣI_{VDD}	Total current into sum of all V_{DD} power lines (source) [1]	120	mA
ΣI_{VSS}	Total current out of sum of all V_{SS} power lines (sink) [1]	-120	
$I_{VDD(PIN)}$	Total current into sum of a single V_{DD} power lines (source) [1]	100	
$I_{VSS(PIN)}$	Total current out of sum of a single V_{SS} power lines (sink) [1]	-100	
$I_{IO(PIN)}$	Current into a single I/O or control pin	+25	
	Current out of a single I/O or control pin	-25	
$\Sigma I_{IO(PIN)}$	Total output current sunk by sum of all I/Os or control pins	+80	
	Total output current sourced by sum of all I/Os or control pins	-80	
$I_{INJ(PIN)}$ [2、3]	Injected current on TC and RST pins	±5	
	Injected current on TTa pins	±5	
$\Sigma I_{INJ(PIN)}$	Total injected current (sum of all I/O and control pins) [4]	±25	

Caution 1: All main power (V_{DD}, V_{DDA}) and ground (V_{SS}, V_{SSA}) pins must always be connected to the external power supply, in the permitted range.

Caution 2: $I_{INJ(PIN)}$ must not exceed its limit to ensure that V_{IN} does not exceed its maximum value. If V_{IN} cannot be guaranteed to not to exceed its maximum value, also ensure that external limit $I_{INJ(PIN)}$ is externally limited to not exceed its maximum value. When $V_{IN} > V_{DD}$, there is a forward injection current; when VIN<VSS, there is a reverse injection current.

Caution 3: Negative injection disturbs the analog performance of the device.

Caution 4: When several inputs are submitted to a current injection, the maximum $\Sigma I_{INJ(PIN)}$ is the absolute sum of the positive and negative injected currents. This result is based on the characterization of the maximum value of $\Sigma I_{INJ(PIN)}$ on the 4 I/O ports of the device.

Table 7-3 Thermal characteristics

Symbol	Ratings	Value	Unit
T_{STG}	Storage temperature range	-65 to +150	°C
T_J	Maximum junction temperature	105	

7.3 Operating conditions

7.3.1 General operating conditions

Table 7-4 General operating conditions

Symbol	Parameter	Conditions	Min.	Max.	Unit
f_{HCLK}	Internal AHB bus frequency	$V_{DD} \geqslant 1.8V$	0	64	MHz
f_{PCLK}	Internal APB bus frequency	$V_{DD} \geqslant 1.8V$	0	64	
f_{HCLK}	Internal AHB bus frequency	$1.65V \leqslant V_{DD} < 1.8V$	0	24	
f_{PCLK}	Internal APB bus frequency	$1.65V \leqslant V_{DD} < 1.8V$	0	24	
V_{DD}	Standard operating voltage	-	1.65	5.5	V
V_{DDA}	Analog operating voltage	Must be equal to V_{DD}	1.65	5.5	V
V_{IN}	I/O input voltage	TC I/O	-0.3	V_{DD} + 0.3	V
		TTa I/O	-0.3	V_{DDA} + 0.3	
		BOOT	0	V_{DD}+0.3	
P_D	Power dissipation at T_A = 85°C for suffix 6 [1]	LQFP100	-	488	mW
		LQFP64	-	435	
T_A	Ambient temperature (suffix 6 version)	Maximum power dissipation	-40	85	°C
		Low power dissipation [2]	-40	105	
T_J	Junction temperature range	Suffix 6 version	-40	105	°C

Caution 1: If T_A is lower, higher P_D values are allowed as long as T_J does not exceed T_{Jmax} (See 8.4 Thermal characteristics).

Caution 2: In low power dissipation state, T_A can be extended to this range as long as T_J does not exceed T_{Jmax} (See 8.4 Thermal characteristics).

7.3.2 Operating conditions at power-up/power-down

The parameters given in the table below are tested under the working conditions listed in *Table 7-4 General operating conditions*.

Table 7-5 Operating conditions at power-up / power-down

Symbol	Parameter	Conditions	Min.	Max.	Unit
t_{VDD}	V_{DD} rise time rate	-	0	∞	µs/V
	V_{DD} fall time rate		20	∞	
t_{VDDA}	V_{DDA} rise time rate	-	0	∞	
	V_{DDA} fall time rate		20	∞	

7.3.3 Embedded reset and power control block characteristics

The parameters given in the table below are tested under the working conditions listed in *Table 7-4 General operating conditions*.

Table 7-6 Embedded reset and power control block characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{POR/BOR}$	Power on/ brown-out reset threshold	Falling edge	1.45 [1]	1.50	1.55 [2]	V
		Rising edge	1.50 [2]	1.55	1.60	V
$V_{BORhyst}$ [3]	BOR hysteresis	-	-	50	-	mV
$t_{RSTTEMPO}$ [3]	Reset temporization	-	4	6.5	13	ms

Caution 1: The product behavior is guaranteed by design down to the minimum $V_{POR/BOR}$ value.

Caution 2: Data based on characterization results, not tested in production.

Caution 3: Guaranteed by design, not tested in production.

7.3.4 Internal reference voltage

Table 7-7 Internal reference voltage

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{REFINT1V5}$	Internal 1.5V reference voltage	-40°C < T_A < +85°C	1.485	1.50	1.515	V
$V_{REFINT2V5}$	Internal 2.5V reference voltage	-40°C < T_A < +85°C	2.475	2.50	2.525	V
ΔV_{REFINT}	Internal reference voltage spread over the temperature range	V_{DDA} = 3V	-	-	10 [1]	mV
T_{Coeff}	Temperature coefficient	-	-60 [1]	-	+60 [1]	ppm/°C

Caution 1: Guaranteed by design, not tested in production.

7.3.5 Supply current characteristics

Current consumption is affected by many factors, such as the operating voltage, ambient temperature, I/O pin loading, device software configuration, operating frequencies, I/O pin switching rate, program location in memory and executed binary code.

Figure 7-4 Method of measurement shows the circuit for testing current consumption.

All result of the Run-mode current consumption measurements based on the same limited code used to test CoreMark.

Typical and maximum current consumption

The MCU is placed under the following conditions:

- All I/O pins are in analog input mode
- All peripherals are disabled except when explicitly mentioned
- The Flash memory access time is adjusted to thef_{HCLK} frequency :
  - 0 wait state inserted when 0 to 24MHz
  - 1 wait state inserted when above 24MHz
  - 2 wait state inserted when above 48MHz
- When the peripherals are enabled $f_{PCLK} = f_{HCLK}$

The data given in Table 7-8 to Table 7-9 are derived from tests performed under the ambient temperature and supply voltage noted in the remarks. For the test conditions, please refer to *Table 7-4 General operating conditions*。

Table 7-8 Typical and maximum current consumption at $V_{DD} = V_{DDA} = 5.5V$

Symbol	Parameter	Conditions	f_{HCLK}	All peripherals enabled		Unit
				Typ.	Max.[1]	
					T_A = 85°C	
I_{DD}[2]	Supply current in Active mode, code executing from Flash	HSI or HSE clock, PLL on	64MHz	13.6	15.0	mA
			48MHz	10.8	11.9	
			24MHz	7.0	7.7	
		HSI or HSE clock, PLL off	8MHz	2.6	2.9	
I_{DD}	Supply current in Active mode, code executing from RAM	HSI or HSE clock, PLL on	64MHz	12.5	13.7	mA
			48MHz	9.5	10.5	
			24MHz	5.2	5.7	
		HSI or HSE clock, PLL off	8MHz	1.9	2.1	mA
I_{DD}	Supply current in Sleep mode, code executing from Flash or RAM	HSI or HSE clock, PLL on	64MHz	9.2	10.2	
			48MHz	7.1	7.8	
			24MHz	3.7	4.4	
		HSI or HSE clock, PLL off	8MHz	1.4	1.6	

Caution 1: Data based on characterization results, not tested in production unless otherwise specified.

Caution 2: I_{DD} is the total current consumption of V_{DD} and V_{DDA}.

Table 7-9 Typical and maximum current consumption in DeepSleep

Symbol	Parameter	Conditions	Typ. @V_{DD} ($V_{DD} = V_{DDA}$)	Max.[1]	Unit
			3.6V	T_A=85°C	
I_{DD}[2]	Supply current in DeepSleep mode	The regulator is in Active mode, all oscillators are off	0.6	8	µA
		The regulator is in Active mode, LSI and IWDT are on	1.7	9	
		The regulator is in Active mode, LSE is on	1.3	8.8	

Caution 1: Data based on characterization results, not tested in production unless otherwise specified.

Caution 2: I_{DD} is the total current consumption of V_{DD} and V_{DDA}.

Typical current consumption

The MCU is placed under the following conditions:

- $V_{DD} = V_{DDA} = 3.3V$
- All I/O pins are in analog input configuration
- The Flash access time is adjusted to f_{HCLK} frequency:
  - 0 wait state inserted when 0 to 24MHz
  - 1 wait state inserted when above 24MHz
  - 2 wait state inserted when above 48MHz
- When the peripherals are enabled, $f_{PCLK} = f_{HCLK}$
- PLL is used for frequencies greater than 8 MHz
- AHB prescaler of 2, 4, 8 and 16 is used for the frequencies 4 MHz, 2 MHz, 1 MHz and 500 kHz respectively

Table 7-10 Typical current consumption in Active mode, program running from FLASH

Symbol	Parameter	Conditions	f_{HCLK}	Typ.		Unit
				Peripherals enabled	Peripherals disabled	
I_{DD} [1]	Supply current in Active mode	Runs from FLASH with 8MHz external crystal oscillator clock	64MHz	13.6	7.1	mA
			48MHz	10.9	6.0	
			8MHz	2.6	1.7	

Caution 1: I_{DD} is the total current consumption of V_{DD} and V_{DDA}.

I/O system current consumption

The current consumption of the I/O system has two components: static and dynamic.

- I/O static current consumption

  All the I/Os used as inputs with pull-up generate current consumption when the pin is externally held low. The value of this current consumption can be simply computed by using the pull-up resistors values given in *Table 7-25 I/O static characteristics*.

  For the output pins, any external pull-down or external load must also be considered to estimate the current consumption.

  If the input voltage level of the I/Os is the intermediate voltage level, it will continuously cause the internal Schmitt trigger to flip, resulting in additional random current consumption (although it is small). If it is required to judge the level flip situation in real time, that should configure the I/Os in analog input mode to avoid this.

Caution 1: Any floating input pin can also settle to an intermediate voltage level or switch inadvertently, as a result of external electromagnetic noise. To avoid current consumption related to floating pins, they must either be configured in analog mode, or forced internally to a definite digital value. This can be done either by using pull-up/down resistors or by configuring the pins in output mode.

- I/O dynamic current consumption

  In addition to the internal peripheral current consumption measured previously, the I/Os used by an application also contribute to the current consumption. When an I/O pin switches, it uses the current from the I/O supply voltage to supply the I/O pin circuitry and to charge/discharge the capacitive load (internal or external) connected to the pin:

$$I_{SW} = V_{DDIOx} \times f_{SW} \times C$$

  where:

  I_{SW} is the current sunk by a switching I/O to charge/discharge the capacitive load.

  V_{DDIOx} is the I/O supply voltage.

  f_{SW} is the I/O switching frequency.

  C is the total capacitance seen by the I/O pin: $C = C_{INT} + C_{EXT} + C_S$

  C_S is the PCB board capacitance including the pad pin.

The test pin is configured in push-pull output mode and is toggled by software at a fixed frequency.

Table 7-11 Switching output I/O current consumption

Symbol	Parameter	Conditions [1]	I/O toggling frequency (f_{SW})	Typ.	Unit
I_{SW}	I/O current consumption	V_{DDIOx} = 3.3V C_{EXT} = 0pF $C = C_{INT} + C_{EXT} + C_S$	4MHz	0.18	mA
			8MHz	0.37	
			16MHz	0.76	
			24MHz	1.39	
		V_{DDIOx} = 3.3V C_{EXT} = 22pF $C = C_{INT} + C_{EXT} + C_S$	4MHz	0.49	
			8MHz	0.94	
			16MHz	2.38	
			24MHz	3.99	
		V_{DDIOx} = 3.3V C_{EXT}= 47pF $C = C_{INT} + C_{EXT} + C_S$	4MHz	0.81	
			8MHz	1.7	
			16MHz	3.67	

Caution 1: C_S = 7pF (estimated value).

7.3.6 Wakeup time from low-power mode

The wakeup times given in the table below are tested during the wake-up phase of the HSIOSC.

The SYSCLK clock source setting is kept unchanged after wakeup from Sleep mode and DeepSleep mode.

All test environments are from ambient temperature and supply voltage conditions summarized in *Table 7-4 General operating conditions*.

Table 7-12 Low-power mode wakeup timings

Symbol	Parameter	Conditions	Typ. @V_{DD} (V_{DD} = V_{DDA})	Max.	Unit
			3.3V		
$t_{WUSLEEP}$	Wakeup from Sleep mode	-	4	-	HCLK
t_{WUDEEP}	Wakeup form DeepSleep mode	Regulator in Active mode	4.0	5.0	μs

7.3.7 External clock source characteristics

High-speed external user clock generated from an external source

In bypass mode the HSE oscillator is switched off and the input pin is a standard GPIO.

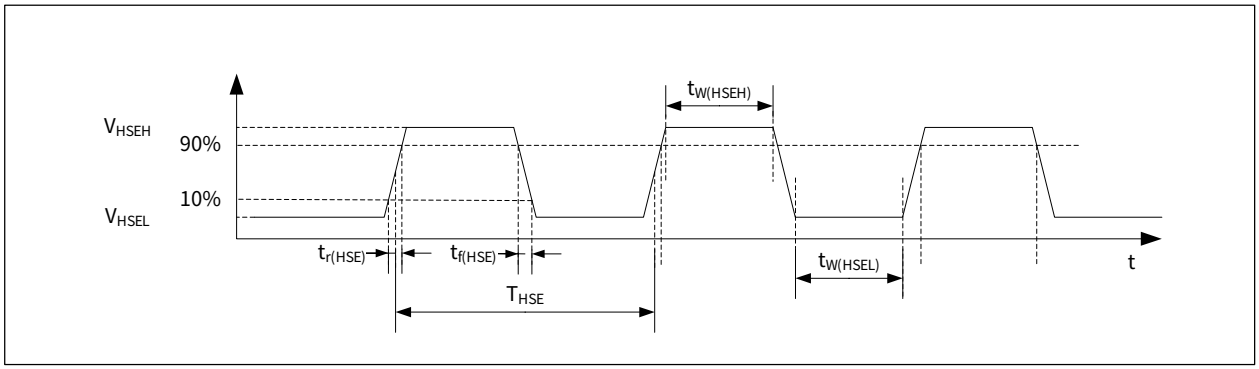
The external clock signal has to respect the I/O characteristics in Section *7.3.12 I/O port characteristics.* The recommended clock input waveform is shown in *Figure 7-5 High-speed external clock source AC timing diagram*.

Table 7-13 High-speed external clock input characteristics

Symbol	Parameter [1]	Min.	Typ.	Max.	Unit
f_{HSE_EXT}	User external clock source frequency	1	-	32	MHz
V_{HSEH}	OSC_IN input pin high level voltage	0.7 V_{DDIOx}	-	V_{DDIOx}	V
V_{HSEL}	OSC_IN input pin low level voltage	V_{SS}	-	0.3 V_{DDIOx}	
$t_{W(HSEH)}$ $t_{W(HSEL)}$	OSC_IN high or low time	15	-	-	ns
$t_{r(HSE)}$ $t_{f(HSE)}$	OSC_IN rise or fall time	-	-	20	

Caution 1: Guaranteed by design, not tested in production.

Figure 7-5 High-speed external clock source AC timing diagram



Low-speed external user clock generated from an external source

In bypass mode the LSE oscillator is switched off and the input pin is a standard GPIO.

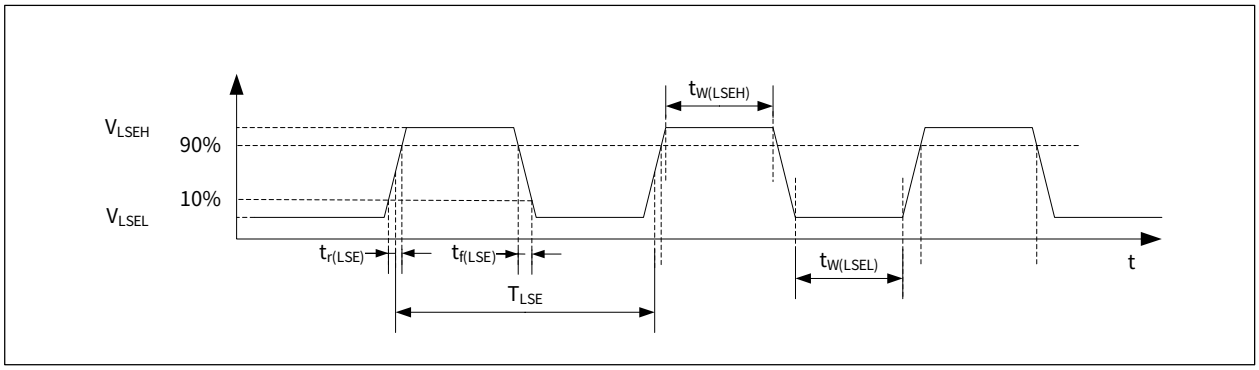
The external clock signal has to respect the I/O characteristics in Section *7.3.12 I/O port characteristics.* The recommended clock input waveform is shown in *Figure 7-6 Low-speed external clock source AC timing diagram*.

Table 7-14 Low-speed external clock input characteristics

Symbol	Parameter [1]	Min.	Typ.	Max.	Unit
f_{LSE_EXT}	User external clock source frequency	-	32.768	1000	kHz
V_{LSEH}	OSC32_IN input pin high level voltage	0.7 V_{DDIOx}	-	V_{DDIOx}	V
V_{LSEL}	OSC32_IN input pin low level voltage	V_{SS}	-	0.3 V_{DDIOx}	
$t_{W(LSEH)}$ $t_{W(LSEL)}$	OSC32_IN high or low time	450	-	-	ns
$t_{r(LSE)}$ $t_{f(LSE)}$	OSC32_IN rise or fall time	-	-	50	

Caution 1: Guaranteed by design, not tested in production.

Figure 7-6 Low-speed external clock source AC timing diagram



High-speed external clock generated from a crystal/ceramic resonator

The high-speed external (HSE) clock can be supplied with a 4 to 32 MHz crystal/ceramic resonator oscillator. All the information given in this paragraph are based on design simulation results obtained with typical external components specified in the table below. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. Refer to the crystal resonator manufacturer for more details on the resonator characteristics (frequency, package, accuracy).

Table 7-15 HSE oscillator characteristics

Symbol	Parameter	Conditions [1]	Min. [2]	Typ.	Max. [2]	Unit
f_{OSC_IN}	Oscillator frequency	-	4	8	32	MHz
R_F	Feedback resistor	-	-	1.4	-	MΩ
I_{DD}	HSE current consumption	During startup [3]	-	-	900	μA
		V_{DD}= 3.3 V, R_m = 45 Ω, C_L = 10 pF@8 MHz	-	430	-	
		V_{DD} = 3.3 V, R_m = 30 Ω, C_L = 20 pF@32 MHz	-	980	-	
$t_{su(HSE)}$ [4]	Startup time	V_{DD} is stabilized	-	2	-	ms

Caution 1: Resonator characteristics given by the crystal/ceramic resonator manufacturer.

Caution 2: Guaranteed by design, not tested in production.

Caution 3: This consumption level occurs during the first 2/3 of the $t_{su(HSE)}$ startup time.

Caution 4: $t_{su(HSE)}$ is the startup time measured from the moment it is enabled (by software) to a stabilized 8 MHz oscillation is reached. This value is measured for a standard crystal resonator and it can vary significantly with the crystal manufacturer.

Low-speed external clock generated from a crystal/ceramic resonator

The low-speed external (LSE) clock can be supplied with a 32.768 kHz crystal/ceramic resonator oscillator. All the information given in this paragraph are based on design simulation results obtained with typical external components specified in the table below. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time. Refer to the crystal resonator manufacturer for more details on the resonator characteristics (frequency, package, accuracy).

Table 7-16 LSE oscillator characteristics (f_{LSE} = 32.768kHz)

Symbol	Parameter [1]	Conditions	Min. [1]	Typ.	Max. [1]	Unit
I_{DD}	LSE current consumption	low drive capability	-	0.35	0.45	μA
		medium-low drive capability	-	0.45	0.60	
		medium-high drive capability	-	0.70	0.90	
		high drive capability	-	1.60	2.00	
$t_{su(LSE)}$ [2]	Startup time	V_{DD} stabilized	-	1.5	-	s

Caution 1: Guaranteed by design, not tested in production.

Caution 2: $t_{su(LSE)}$ is the startup time measured from the moment it is enabled (by software) to a stabilized 32.768 kHz oscillation is reached. This value is measured for a standard crystal and it can vary significantly with the crystal manufacturer.

7.3.8 Internal clock source characteristics

The data given in the following table is based on the sample tests of the test environment indicated by *Table 7-4 General operating conditions*.

High-speed internal (HSIOSC) RC oscillator

Table 7-17 HSI oscillator characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f_{HSI}	Frequency	-	-	48	-	MHz
TRIM	HSI user trimming step	-	-	0.2	-	%
$Duty_{HSI}$	Duty cycle	-	45	-	55	%
ACC_{HSI}	Accuracy of the HSI oscillator (factory calibrated)	T_A = -40°C ~ +85°C	-2.0	-	+2.0	%
		T_A = +25°C	-0.5	-	+0.5	%
$t_{SU(HSI)}$	HSI oscillator startup time	-	3	-	5	μs
$I_{DDA(HSI)}$	HSI oscillator power consumption	-	-	600	-	μA

Low-speed internal (LSI) RC oscillator

Table 7-18 LSI oscillator characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f_{LSI}	Frequency	-	-	32.8	-	kHz
TRIM	LSI user trimming step	-	-	1	-	%
$Duty_{LSI}$	Duty cycle	-	45	-	55	%
ACC_{LSI}	Accuracy of the LSI oscillator (factory calibrated)	T_A = -40°C ~ +85°C	-3	-	+3	%
		T_A = +25°C	-1	-	+1	%
$t_{SU(LSI)}$	LSI oscillator startup time	-	-	-	50	μs
$I_{DDA(LSI)}$	LSI oscillator power consumption	-	-	1	-	μA

Ultra-Low-Speed Internal (RC10K) RC Oscillator

Table 7-19 RC10K oscillator characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f_{RC10K}	Frequency	-	-	8.5	-	kHz
$Duty_{RC10K}$	Duty cycle	-	45	-	55	%
ACC_{RC10K}	Accuracy of the RC10K oscillator(factory calibrated)	T_A = -40°C ~ +85°C	-50	-	+50	%
		T_A = +25°C	-20	-	+20	%

Mid-low-speed internal (RC150K) RC oscillator

Table 7-20 RC150K oscillator characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f_{RC150K}	Frequency	-	-	120	-	kHz
$Duty_{RC150K}$	Duty cycle	-	45	-	55	%
ACC_{RC150K}	Accuracy of the RC150K oscillator(factory calibrated)	T_A = -40°C ~ +85°C	-50	-	+50	%
		T_A = +25°C	-20	-	+20	%

7.3.9 PLL characteristics

The data given in the following table is based on the sample tests of the test environment indicated by *Table 7-4 General operating conditions*.

Table 7-21 PLL characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit
f_{PLL_IN}	Frequency	4	-	24	MHz
	Duty cycle	40	-	60	%
f_{PLL_OUT}	PLL multiplier output	8	-	64	MHz
t_{LOCK}	PLL lock time	-	100	200	μs
$Jitter_{PLL}$	Cycle-to-cycle jitter	-	-	300	ps

7.3.10 Memory characteristics

FLASH memory

The characteristics are for 40°C to +85°C test enviroment unless otherwise specified.

Table 7-22 FLASH memory characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max. [1]	Unit
t_{prog8}	8-bit programming time	T_A = -40°C ~ +85°C	-	30	-	μs
t_{prog16}	16-bit programming time	T_A = -40°C ~ +85°C	-	37	-	μs
t_{prog32}	32-bit programming time	T_A = -40°C ~ +85°C	-	51	-	μs
t_{ERASE}	Page erase time	T_A = -40°C ~ +85°C	-	4.6	-	ms
t_{ME}	Mass erase time	T_A = -40°C ~ +85°C	-	35	-	ms
I_{DD}	Supply current	Write mode	-	-	3.5	mA
		Erase mode	-	-	2	mA
V_{prog}	Programming voltage	-	1.65	-	5.5	V

Caution 1: Guaranteed by design, not tested in production.

Table 7-23 FLASH memory endurance and data retention

Symbol	Parameter	Conditions	Min. [1]	Unit
N_{NED}	Endurance	T_A = -40°C ~ +85°C	20000	Times
t_{RET}	Data retention	T_A = 25°C	100	Years
		T_A = 85°C	25	

Caution 1: Obtained by comprehensive evaluation, not tested in production.

7.3.11 ESD characteristics

Use specific measurement methods to test the strength of the chip to determine its electrical sensitivity performance.

Table 7-24 ESD characteristics

Symbol	Parameter	Condition	Typ.	Max.	Unit
$V_{ESD(HBM)}$	Electrostatic discharge voltage (human body model)	T_A = +25 ° C, conforming to JESD22-A115C	-	8	kV
$V_{ESD(CDM)}$	Electrostatic discharge voltage (charge device model)	T_A = +25 ° C, conforming to JESD22-A115C	-	2	

7.3.12 I/O port characteristics

General input/output characteristics

Unless otherwise stated, the test data given in the table below is based on the test environment indicated by *Table 7-4 General operating conditions*.

All I/Os are designed as CMOS- and TTL-compliant.

Table 7-25 I/O static characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{IL}	Low level input voltage	TC and TTa I/O	-	-	0.3 V_{DDIOx}	V
V_{IH}	High level input voltage	TC and TTa I/O	0.7 V_{DDIOx}	-	-	V
V_{hys}	Schmitt trigger hysteresis	TC and TTa I/O	-	400 [1]	-	mV
I_{ikg}	Input leakage current	TC and TTa I/O in digital mode $V_{SS} \leqslant V_{IN} \leqslant V_{DDIOx}$	-	-	±0.1	µA
		TTa I/O in digital mode $V_{DDIOx} \leqslant V_{IN} \leqslant V_{DDA}$	-	-	1	
		TTa I/O in analog mode $V_{SS} \leqslant V_{IN} \leqslant V_{DDA}$	-	-	±0.2	
R_{PU} [2]	Weak pull-up equivalent resistor	$V_{IN} = V_{SS}$	50	80	180	kΩ
R_{PD} [2]	Weak pull-down equivalent resistor	$V_{IN} = V_{DDIOx}$	20	30	45	kΩ
C_{IO}	I/O pin capacitance	-	-	5	-	pF

Caution 1: Data based on design simulation only. Not tested in production.

Caution 2: Pull-up and pull-down resistors are designed with a true resistance in series with a switchable PMOS/NMOS. This PMOS/NMOS contribution to the series resistance is minimal.

Output driving current

The GPIOs can sink or source up to ±8mA, and sink or source up to ±20mA with a relaxed V_{OH} and V_{OL}.

In the user application, the number of I/O pins which can drive current must be limited to respect the absolute maximum rating specified in Section *7.2 Absolute maximum ratings*:

- The sum of the currents sourced by all the I/Os on V_{DDIOx}, plus the maximum consumption of the MCU sourced on V_{DD} , cannot exceed the absolute maximum rating ΣI_{VDD} (see *Table 7-1 Voltage characteristics*[1]).
- The sum of the currents sunk by all the I/Os on V_{SS} , plus the maximum consumption of the MCU sunk on V_{SS} , cannot exceed the absolute maximum rating ΣI_{VSS} (see *Table 7-1 Voltage characteristics*[1]).

Output voltage levels

Unless otherwise stated, the test data given in the table below is based on the test environment indicated by *Table 7-4 General operating conditions*.

All I/Os are designed as CMOS- and TTL-compliant.

Table 7-26 Output voltage characteristics

Symbol	Parameter	Conditions	Min.	Max.	Unit
V_{OH}	High-level output voltage source current	Sourcing 10mA, V_{DD} = 3.3V[1]	3.02	-	V
		Sourcing 20mA, V_{DD} = 3.3V[2]	2.7	-	
V_{OL}	Low-level output voltage sink current	Sinking 10mA, V_{DD} = 3.3V[1]	-	0.23	
		Sinking 20mA, V_{DD} = 3.3V[2]	-	0.45	

Caution 1: The maximum total current I_{OH}(max) and I_{OL}(max) of all output combinations should not exceed 40mA to meet the maximum specified voltage drop.

Caution 2: The maximum total current I_{OH}(max) and I_{OL}(max) of all output combinations should not exceed 100mA to meet the maximum specified voltage drop.

Input/output AC characteristics

The values and definitions of the AC characteristics of the I/Os are given by the following charts respectively.

Unless otherwise stated, the test data given in the table below is based on the test environment indicated by *Table 7-4 General operating conditions*.

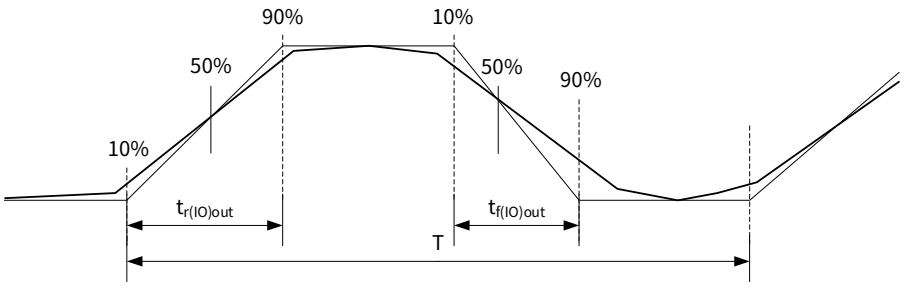
Table 7-27 I/O AC characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
$f_{max(IO)out}$	Maximum frequency [2]	C_L = 30pF，V_{DDIOx} ≥ 2.7V	-	50	MHz
		C_L = 50pF，V_{DDIOx} ≥ 2.7V	-	30	
		C_L = 50pF，2.4V ≤ V_{DDIOx} < 2.7V	-	20	
$t_{f(IO)out}$	Output fall time	C_L = 30pF，V_{DDIOx} ≥ 2.7V	-	5	ns
		C_L = 50pF，V_{DDIOx} ≥ 2.7V	-	8	
		C_L = 50pF，2.4V ≤ V_{DDIOx} < 2.7V	-	12	
$t_{r(IO)out}$	Output rise time	C_L = 30pF，V_{DDIOx} ≥ 2.7V	-	5	
		C_L = 50pF，V_{DDIOx} ≥ 2.7V	-	8	
		C_L = 50pF，2.4V ≤ V_{DDIOx} < 2.7V	-	12	

Caution 1: Data based on design simulation only. Not tested in production.

Caution 2: The maximum frequency is defined in the figure below.

Figure 7-7 I/O AC characteristics definition



Maximum frequency is achieved if ($t_r + t_f$) ≤ 2/3T and if the duty cycle is (45-55%) when loaded by C_L

7.3.13 NRST pin characteristics

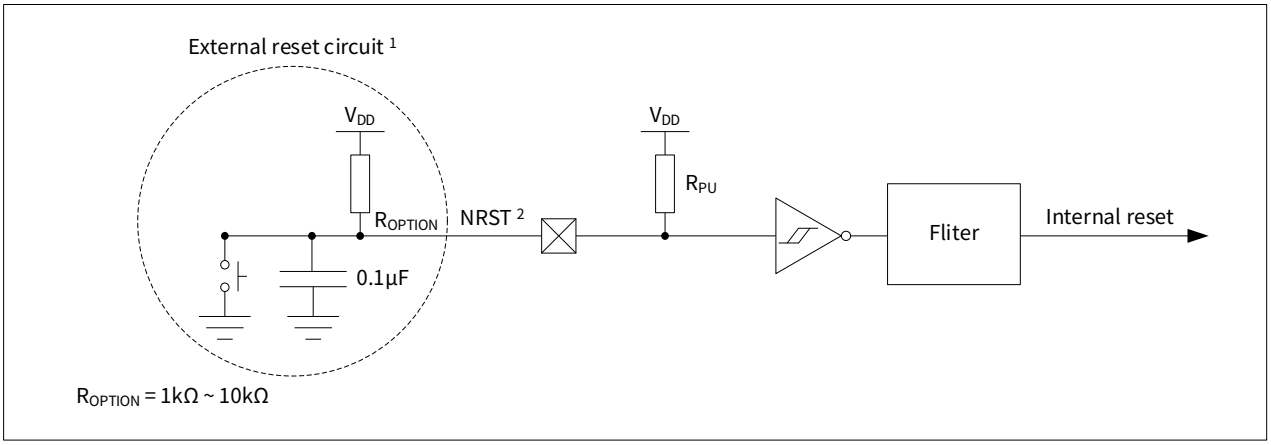
The NRST pin is connected to a permanent pull-up resistor R_{PU} internally.

Unless otherwise stated, the test data given in the table below is based on the test environment indicated by *Table 7-4 General operating conditions*.

Table 7-28 NRST pin characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{IL(NRST)}$	NRST input low level voltage	-	-	-	$0.3V_{DD}$	V
$V_{IH(NRST)}$	NRST input high level voltage	-	$0.7V_{DD}$	-	-	-
$V_{hys(NRST)}$	NRST input voltage hysteresis	-	-	200	-	mV
R_{PU}	Weak pull-up equivalent resistor	$V_{IN} = V_{SS}$	7	8	9	kΩ
$V_{F(NRST)}$	Minimum required reset pulse width	-	20	-	-	μs

Figure 7-8 Recommended NRST pin protection



Caution 1: The external capacitor protects the device against parasitic resets.

Caution 2: The user must ensure that the level on the NRST pin can go below the $V_{IL(NRST)}$ max level specified in Table 7-28 NRST pin characteristics. Otherwise the reset will not be taken into account by the device.

7.3.14 12-bit ADC characteristics

Unless otherwise stated, the test data given in the table below is based on the test environment indicated by *Table 7-4 General operating conditions.*

Table 7-29 ADC characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{DDA}	Analog supply voltage for ADC ON	-	1.65	-	5.5	V
$I_{DDA(ADC)}$	Current consumption of the ADC	$V_{DD} = V_{DDA} = 3.3V$	-	1.5	-	mA
f_{ADC}	ADC clock frequency	-	-	24	-	MHz
f_S	Sampling rate	-	-	-	1	MHz
f_{TRIG}	External trigger frequency	$f_{ADC} = 24MHz$	-	-	800	kHz
V_{AIN}	Conversion voltage range	-	0	-	V_{DDA}	V
R_{AIN}	Input impedance	-	-	-	100	kΩ
C_{ADC}	Internal sample and hold capacitor	-	-	9	-	pF
t_S	Sampling time	-	5	-	10	$1 / f_{ADC}$
t_{STAB}	Stabilization time	-	19			$1 / f_{ADC}$
t_{CONV}	Total conversion time (including sampling time)	-	24	-	29	$1 / f_{ADC}$

Table 7-30 Accuracy of ADC[1]

Symbol	Parameter	Conditions	Min.	Typ.	Max. [2]	Unit
ET	Composite error	f_{ADC} = 24MHz, V_{DDA} = 1.65V ~ 5.5V, T_A = -40°C ~+85°C	-	±2.5	±3.0	LSB
EO	Offset error		-	±1.5	±2.4	
EG	Gain error		-	±2.2	±2.7	
DNL	Differential nonlinearity		-	±0.5	±1.0	
INL	Integral nonlinearity		-	±1.0	±3.0	
SINAD	Signal-to-noise ratio distortion		-	67	-	dB
SNR	Signal-to-noise ratio		-	66	-	
THD	Total harmonic distortion		-	-70	-	
ENOB	Significant digits	V_{ref} = V_{DDA}/ExRef 25KSPS@V_{DDA} = 1.65V~1.8V 100KSPS@V_{DDA} = 1.8V~2V 200KSPS@V_{DDA} = 2V~2.4V	-	10.3	-	bits
		V_{ref} = V_{DDA}/ExRef 500KSPS@V_{DDA} = 2.4V~2.7V 1MSPS@V_{DDA} = 2.7V~5.5V	-	10.8	-	
		V_{ref} = Internal 1.5V reference voltage 100KSPS@V_{DDA} = 1.8V~2V 200KSPS@V_{DDA} = 2V~5.5V	-	9.7	-	
		V_{ref} = Internal 2.5V reference voltage 200KSPS@V_{DDA} = 2.8V~5.5V	-	10.1	-	

Caution 1 : ADC DC accuracy values are measured after internal calibration;

Avoid injecting reverse current on any analogue input pin as this can degrade the accuracy of conversions performed on another analogue input, it is recommended to add a Schottky diode (between the pin and ground) to the analogue pin where the reverse current will probably be injected;

Better performance can be achieved over restricted V_{DDA}, frequency, and temperature ranges.

Caution 2 : Data based on characterization results, not tested in production.

7.3.15 Temperature sensor characteristics

Table 7-31 TS characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit
T_L	VSENSE linearity with temperature	-	±2	±5	°C
Avg_Slope	Average slope	2.66	2.69	2.72	mV / °C
V_{25}	Voltage at 25°C（±5°C）	0.77	0.79	0.8	V
t_{START}	TS internal temperature sensor follower settling time	-	-	45	μs
t_{S_temp}	ADC sampling time when reading the temperature	5	-	-	μs

7.3.16 Analog voltage comparator characteristics

Table 7-32 Comparator characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max. [1]	Unit
V_{DDA}	Analog supply volgate	-	1.65	-	5.5	V
V_{IN}	Comparator input volgate range	-	0	-	V_{DDA}	V
t_{START}	Startup time	Ultra low speed	-	10	10	μs
		Low speed	-	1	2	
		Medium speed	-	0.5	1	
		High speed	-	0.1	0.25	
t_D	Delay Time	Ultra low speed	-	10	10	
		Low speed	-	1	2	
		Medium speed	-	0.5	1	
		High speed	-	0.2	0.5	
V_{offset}	Offset Error	-	-	±3	±10	mV
dThreshold/dt	Threshold voltage temperature coefficient	V_{DD} = 3.3V, -40°C < T_A < +85°C , V- = (n/64)×V_{ref}	-	40	80	ppm/°C
$I_{DD(VC)}$	Current consumption	Ultra low speed	-	0.2	0.3	μA
		Low speed	-	1	1.2	
		Medium speed	-	8	10	
		High speed	-	16	20	
V_{hys}	Comparator hysteresis	Nohysteresis (VCx_CR0.HYS=00)	-	0	-	mV
		Low hysteresis (VCx_CR0.HYS=01)	-	10	-	
		Medium hysteresis (VCx_CR0.HYS=10)	-	20	-	
		High hysteresis (VCx_CR0.HYS=11)	-	30	-	

Caution 1: Data based on characterization results, not production tested.

7.3.17 Programmable low voltage detector characteristics

Table 7-33 Programmable low voltage detector characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{IN}	Input voltage range	-	0	-	V_{DDA}	V
V_{TH}	Detection threshold	LVD_CR0.VTH=0	0.95 V_{TH}	1.8	1.05 V_{TH}	V
		LVD_CR0.VTH=1		1.9		
		LVD_CR0.VTH=2		2.0		
		LVD_CR0.VTH=3		2.1		
		LVD_CR0.VTH=4		2.2		
		LVD_CR0.VTH=5		2.3		
		LVD_CR0.VTH=6		2.4		
		LVD_CR0.VTH=7		2.5		
		LVD_CR0.VTH=8		2.6		
		LVD_CR0.VTH=9		2.7		
		LVD_CR0.VTH=10		2.8		
		LVD_CR0.VTH=11		2.9		
		LVD_CR0.VTH=12		3.0		
		LVD_CR0.VTH=13		3.1		
		LVD_CR0.VTH=14		3.2		
		LVD_CR0.VTH=15		3.3		
I_{DD}	Power consumption	Filter disabled	-	280	-	nA
		Filter enabled	-	1600	-	
t_{resp}	Response time	-	-	80	-	μs
t_{setup}	Set-up time	-	-	150	-	μs
V_{hys}	Hysteresis voltage	-	-	40	-	mV

7.3.18 LCD controller

Table 7-34 LCD Controller Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{LCD4}	LCD adjustable maximum voltage	-	-	-	V_{DD}	V
V_{LCD3}	LCD maximum voltage	-	-	-	V_{LCD4}	
V_{LCD2}	LCD 2/3 voltage	-	-	-	2/3 V_{LCD4}	
V_{LCD1}	LCD 1/3 voltage	-	-	-	1/3 V_{LCD4}	
I_{LCD}	Working current	V_{DD} = 3.3V, Internal resistor divider CR0.INRS=4	2.16	2.7	3.24	μA
		V_{DD} = 3.3V, Internal resistor divider CR0.INRS=2	4	5	6	
		V_{DD} = 3.3V, Internal resistor divider CR0.INRS=1	22.4	28	33.6	
		V_{DD} = 3.3V, Internal resistor divider CR0.INRS=7	28	35	42	
		V_{DD} = 3.3V, External resistor divides four resistors with a resistance value of 27kΩ	-	30	-	
		V_{DD} = 3.3V, External capacitor divider	-	0.2	-	
R_H	Low drive resistance	-	1000	1200	1400	kΩ
R_L	High drive resistance	-	70	90	110	
ΔV_{XX}	LCD Voltage deviation	-40°C <T_A < +85°C	-100	-	+100	mV

7.3.19 Timer characteristics

The parameters given in the following tables are guaranteed by design.

Refer to Section *7.3.12 I/O port characteristics* for details on the input/output alternate function characteristics (output compare, input capture, external clock, PWM output).

Table 7-35 Timer characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$T_{res(TIM)}$	Timer resolution	-	-	1	-	t_{TIMCLK}
		f_{TIMCLK} = 64MHz	-	15.6	-	ns
f_{EXT}	Timer external clock frequency	-	-	-	f_{TIMCLK} / 2	MHz
t_{MAX_COUNT}	Maximum period	-	-	-	65536	t_{TIMCLK}

Table 7-36 IWDT min/max timeout period at 10 kHz (RC10K)

Frequency division factor	IWDT_CR.PRS	Min timeout period	Max timeout period	Unit
4	0	0.417	2560	ms
8	1	0.834	5120	
16	2	1.667	10240	
32	3	3.334	20480	
64	4	6.667	40960	
128	5	13.334	81920	
256	6	26.667	163840	
512	7	53.334	327680	

Table 7-37 WWDT min/max timeout period at 64 MHz（PCLK）

Frequency division factor	Control bit	Min timeout period	Max timeout period	Unit
4096	0	0.064	2.56	ms
8192	1	0.128	5.12	
16384	2	0.256	10.24	
32768	3	0.512	20.48	
65536	4	1.024	40.96	
131072	5	2.048	81.92	
262144	6	4.096	163.82	
524288	7	8.192	327.68	

7.3.20 Communication interfaces

I2C interface characteristics

- The I2C interface meets the I2C-bus specification and the user manual:
  - Standard-mode (Sm): with a bit rate up to 100 kbit/s
  - Fast-mode (Fm) : with a bit rate up to 400 kbit/s
  - Fast-mode Plus (Fm+): with a bit rate up to 1 Mbit/s
- The I2C timings requirements are guaranteed by design when the I2C peripheral is properly configured (refer to Reference manual).
- The SDA and SCL I/O requirements are met with the following restrictions:
  - The SDA and SCL I/O pins are not "true" open-drain,maximum input voltage limited by specification.

    When configured as open-drain, the PMOS connected between the I/O pin and V_{DDIOx} is disabled, but is still present.

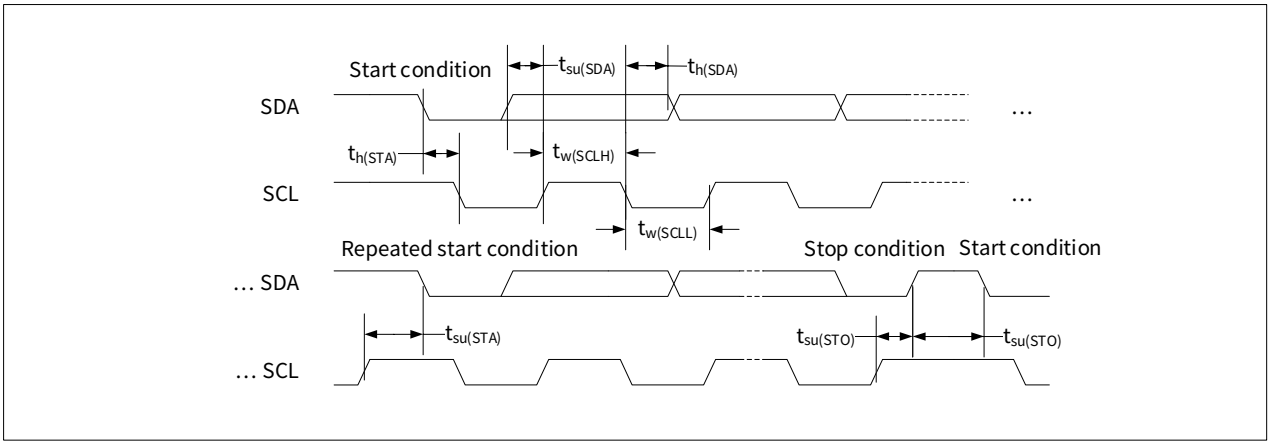
Refer to Section *7.3.12 I/O port characteristics* for the I2C I/Os characteristics.

Table 7-38 I2C characteristics

Symbol	Parameter	Standard mode (100K)		Fast mode (400K)		High speed mode (1M)		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{w(SCLL)}$	SCL clock low time	4.7	-	1.25	-	0.5	-	μs
$t_{w(SCLH)}$	SCL clock high time	4.0	-	0.6	-	0.26	-	
$t_{su(SDA)}$	SDA setup time	250	-	100	-	50	-	ns
$t_{h(SDA)}$	SDA data hold time	0	-	0	-	0	-	
$t_{h(STA)}$	Start condition hold time	2.5	-	0.625	-	0.25	-	μs
$t_{su(STA)}$	Repeated Start Condition Startup Time	2.5	-	0.6	-	0.25	-	
$t_{su(STO)}$	Stop condition setup time	0.25	-	0.25	-	0.25	-	
$t_{w(STO:STA)}$	Stop condition to start condition time(Bus Idle)	4.7	-	1.3	-	0.5	-	

Caution 1: Guaranteed by design, not tested in production.

Figure 7-9 I2C timing diagram



SPI interface characteristic parameters

Table 7-39 SPI characteristics

Symbol	Parameter	Conditions	Min.	Max.	Unit
$t_{c(SCK)}$	SPI clock frequency	Master mode $f_{PCLK} \geqslant 32MHz$	62.5	-	ns
		Slave mode $f_{PCLK} \geqslant 48MHz$	83.3	-	
$t_{su(NSS)}$	NSS setup time	Slave mode	$0.5 \times t_{c(SCK)}$	-	
$t_{h(NSS)}$	NSS hold time	Slave mode	$0.5 \times t_{c(SCK)}$	-	
$t_{w(SCKH)}$ $t_{w(SCKL)}$	SCK high and low setup time	Master mode/Slave mode	$0.5 \times t_{c(SCK)}$	-	
$t_{su(MI)}$ $t_{su(SI)}$	Data input setup time	Master mode	10	-	
		Slave mode	10	-	
$t_{h(MI)}$ $t_{h(SI)}$	Data input hold time	Master mode	2	-	
		Slave mode	2	-	
$t_{v(SO)}$	Data output valid time	Slave mode f_{PCLK}= 64MHz	-	50	
$t_{v(MO)}$		Master mode f_{PCLK}= 32MHz	-	3	
$t_{h(SO)}$	Data output hold time	Slave mode	30	-	
$t_{h(MO)}$		Master mode f_{PCLK}= 32MHz	2	-	

Caution 1: Data based on characterization results, not tested in production.

Figure 7-10 SPI timing diagram - slave mode and CPHA=0

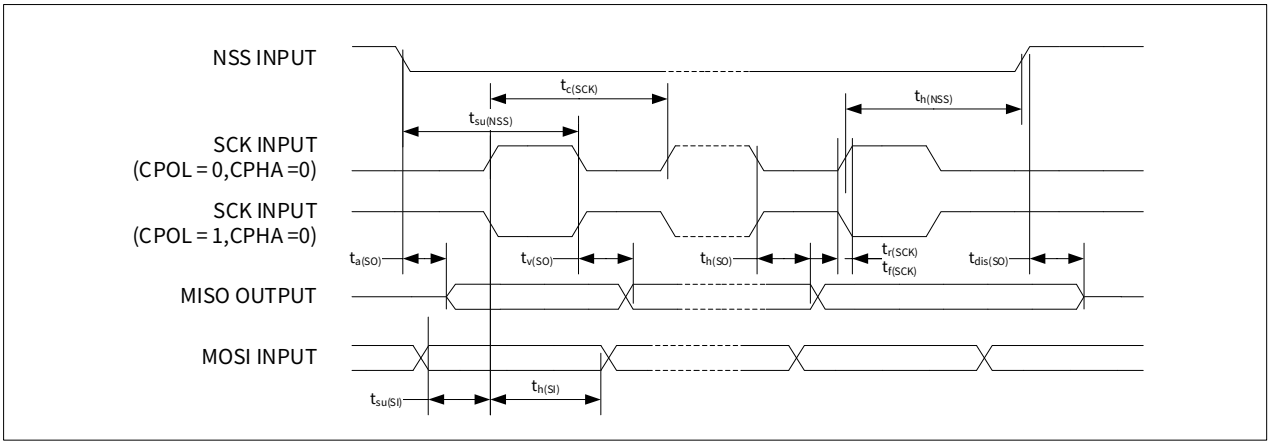


Figure 7-11 SPI timing diagram - slave mode and CPHA=1

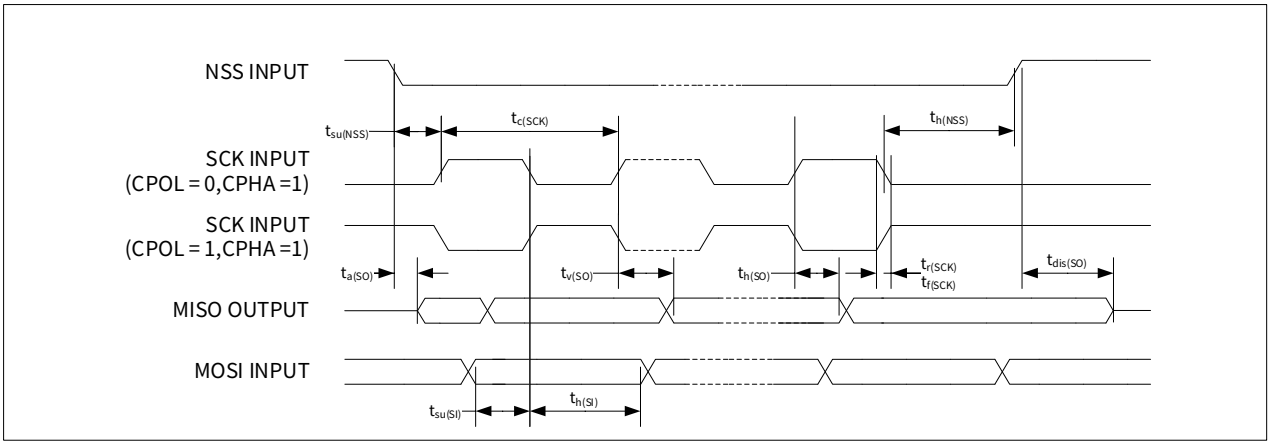
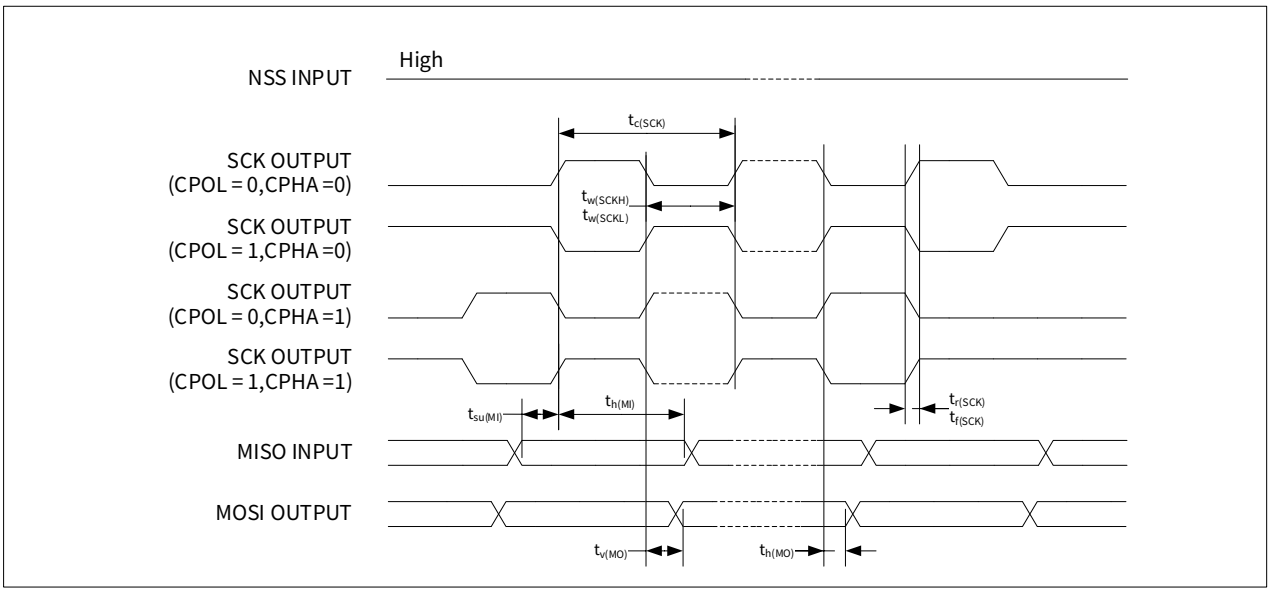


Figure 7-12 SPI timing diagram - master mode

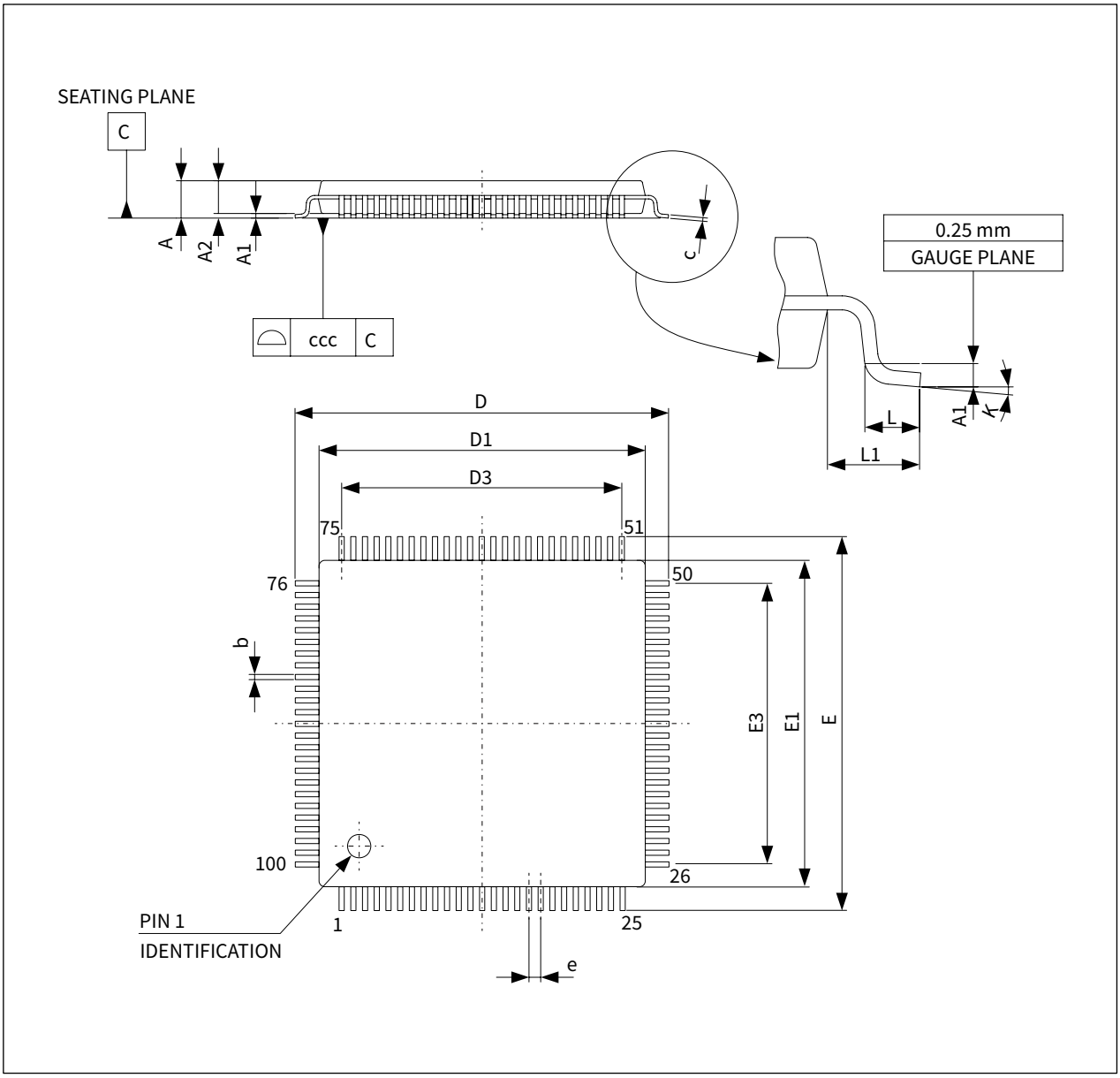


8 Package information

8.1 LQFP100 package information

LQFP100 is 100-pin, 14 x 14mm low-profile quad flat package.

Figure 8-1 LQFP100 outline



Caution 1: Drawing is not to scale.

Table 8-1 LQFP100 mechanical data

Symbol	Millimeters			Inches [1]		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	15.800	16.000	16.200	0.6220	0.6299	0.6378
D1	13.800	14.000	14.200	0.5433	0.5512	0.5591
D3	-	12.000	-	-	0.4724	-
E	15.800	16.000	16.200	0.6220	0.6299	0.6378
E1	13.800	14.000	14.200	0.5433	0.5512	0.5591
E3	-	12.000	-	-	0.4724	-
e	-	0.500	-	-	0.0197	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0°	3.5°	7°	0°	3.5°	7°
ccc	-	-	0.080	-	-	0.0031

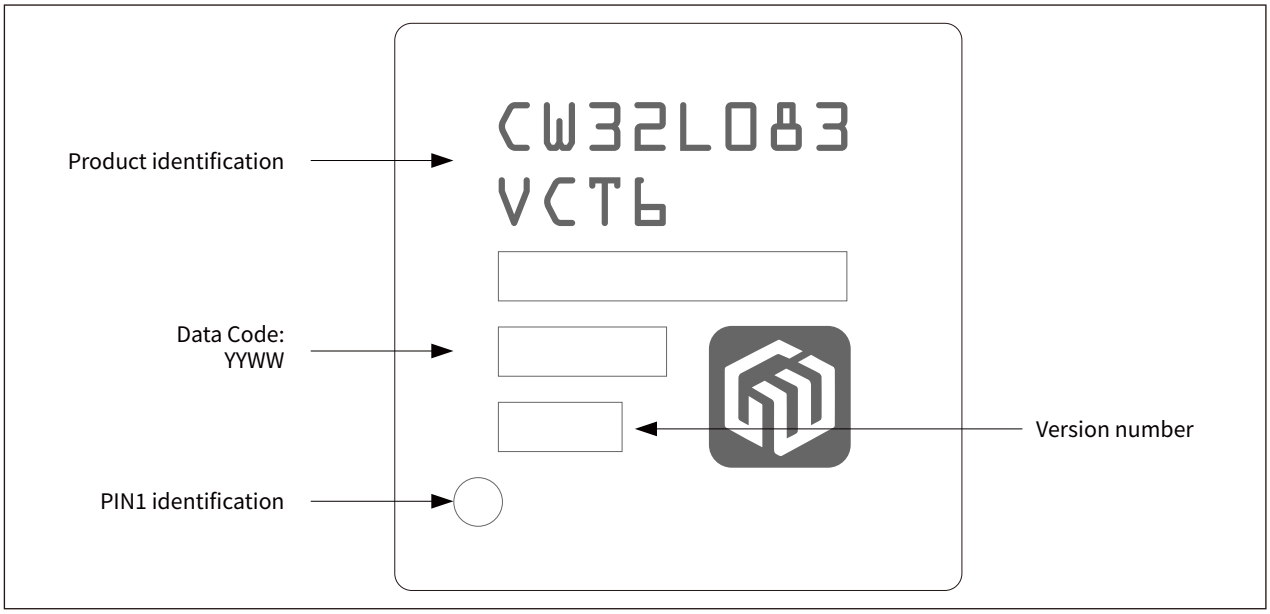
Caution 1: Values in inches are converted from mm and rounded to 4 decimal digits.

Device marking

The following figure gives an example of topside marking orientation versus pin 1 identifier location.

The printed markings may differ depending on the supply chain. Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

Figure 8-2 LQFP100 topside marking example

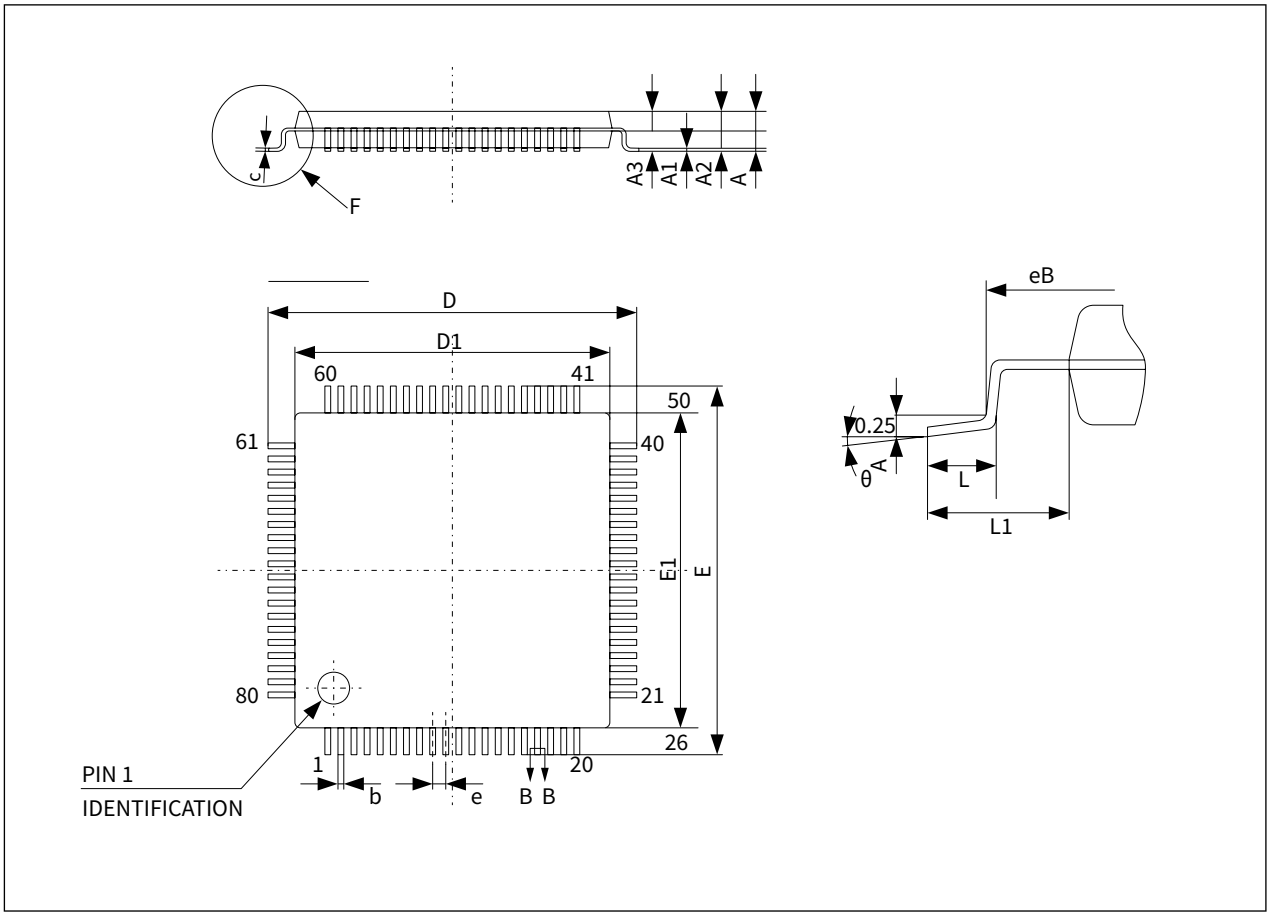


Caution 1: Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. CW is not responsible for any consequences resulting from such use. In no event will CW be liable for the customer using any of these engineering samples in production. CW's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

8.2 LQFP80 package information

LQFP80 is a 80-pin, 12 x 12mm low-profile quad flat package.

Figure 8-3 LQFP80 outline



Caution 1: Drawing is not to scale.

Table 8-2 LQFP80 mechanical data

Symbol	Millimeters			Inches [1]		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.60	-	-	0.0630
A1	0.05	-	0.15	0.0020	-	0.0059
A2	1.35	1.400	1.45	0.0531	0.0551	0.0571
A3	0.59	0.64	0.69	0.0232	0.0252	0.0272
b	0.18	-	0.26	0.0071	-	0.0102
b1	0.17	0.20	0.23	0.0067	0.0079	0.0091
c	0.13	-	0.17	0.0051	-	0.0067
D	13.80	14.00	14.20	0.5433	0.5512	0.5591
D1	11.90	12.00	12.10	0.4685	0.4724	0.4764
E	13.80	14.00	14.20	0.5433	0.5512	0.5591
E1	11.90	12.00	12.10	0.4685	0.4724	0.4764
eB	13.05	-	13.25	0.5138	-	0.5217
e	0.50 BSC			0.0197 BSC		
L	0.45	0.60	0.75	0.0177	0.0236	0.0295
L1	1.00 REF			0.0394 REF		
θ	0°	-	7°	0°	-	7°

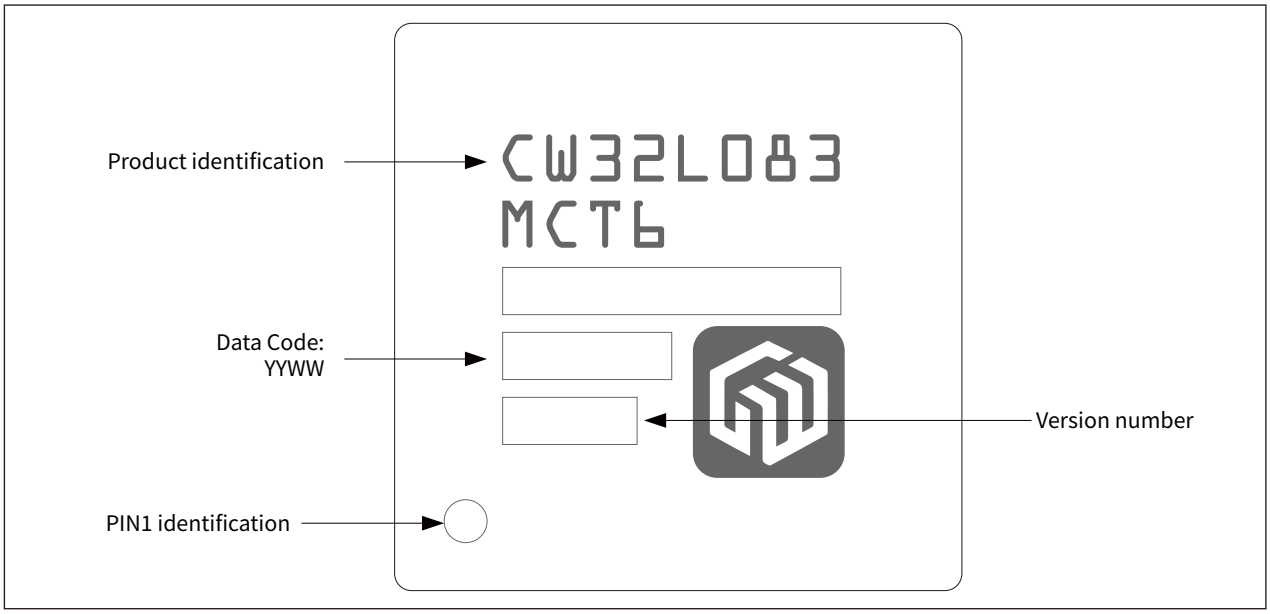
Caution 1: Values in inches are converted from mm and rounded to 4 decimal digits.

Device marking

The following figure gives an example of topside marking orientation versus pin 1 identifier location.

The printed markings may differ depending on the supply chain. Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

Figure 8-4 LQFP80 topside marking example

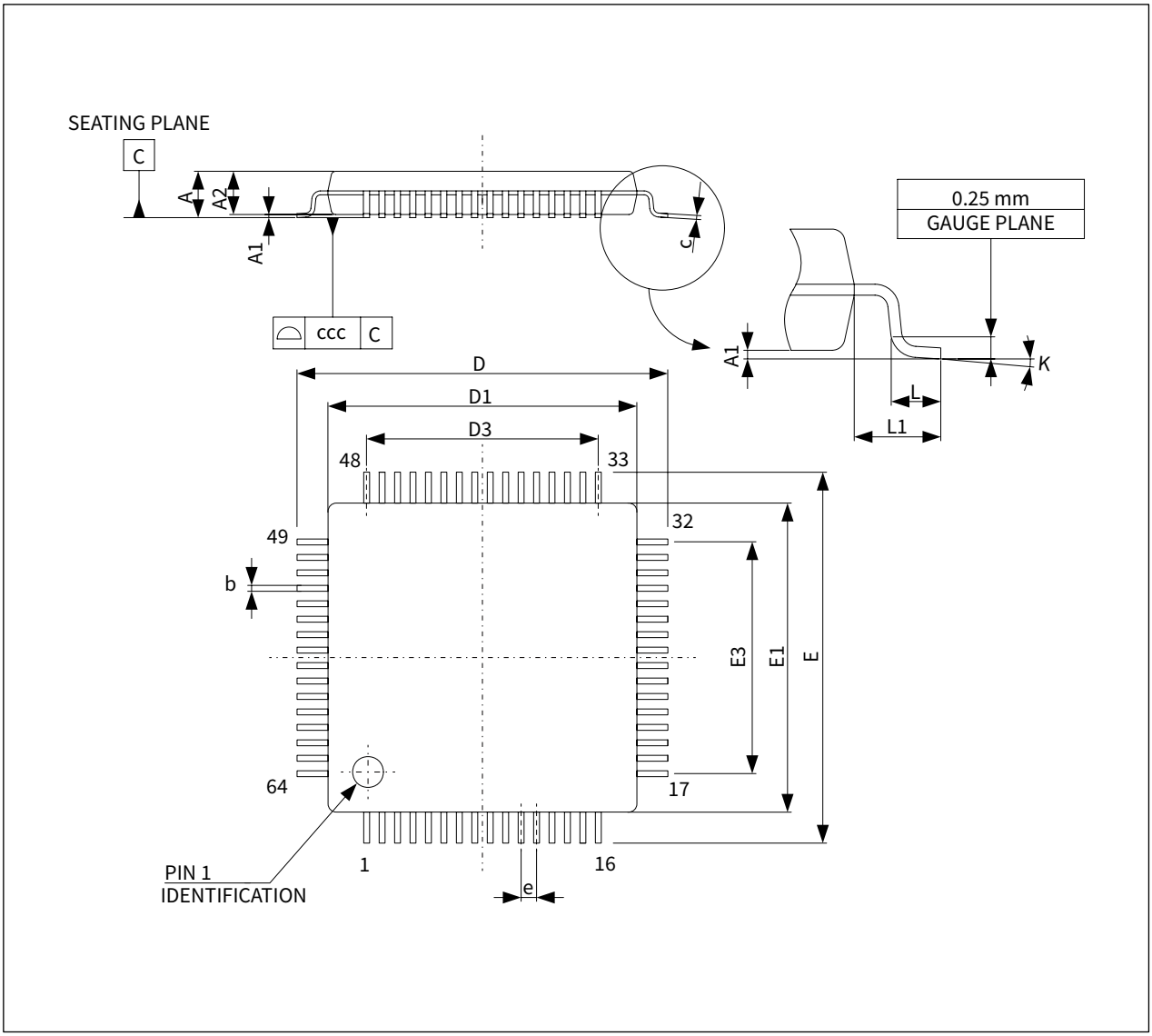


Caution 1: Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. CW is not responsible for any consequences resulting from such use. In no event will CW be liable for the customer using any of these engineering samples in production. CW's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

8.3 LQFP64 (10mm×10mm) package information

LQFP64 is a 64-pin, 10 x 10mm low-profile quad flat package.

Figure 8-5 LQFP64 (10mm×10mm) outline



Caution 1: Drawing is not to scale.

Table 8-3 LQFP64 (10mm×10mm) mechanical data

Symbol	Millimeters			Inches [1]		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	-	12.000	-	-	0.4724	-
D1	-	10.000	-	-	0.3937	-
D3	-	7.500	-	-	0.2953	-
E	-	12.000	-	-	0.4724	-
E1	-	10.000	-	-	0.3937	-
E3	-	7.500	-	-	0.2953	-
e	-	0.500	-	-	0.0197	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0°	3.5°	7°	0°	3.5°	7°
ccc	-	-	0.080	-	-	0.0031

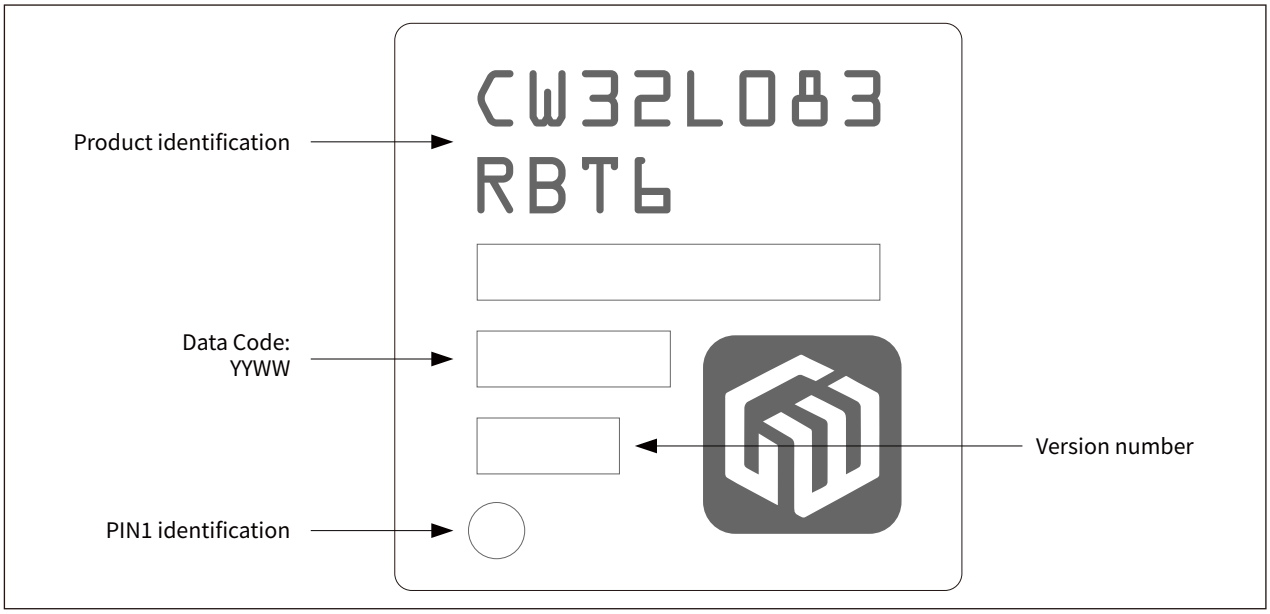
Caution 1: Values in inches are converted from mm and rounded to 4 decimal digits.

Device marking

The following figure gives an example of topside marking orientation versus pin 1 identifier location.

The printed markings may differ depending on the supply chain. Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

Figure 8-6 LQFP64 (10mm×10mm) topside marking example

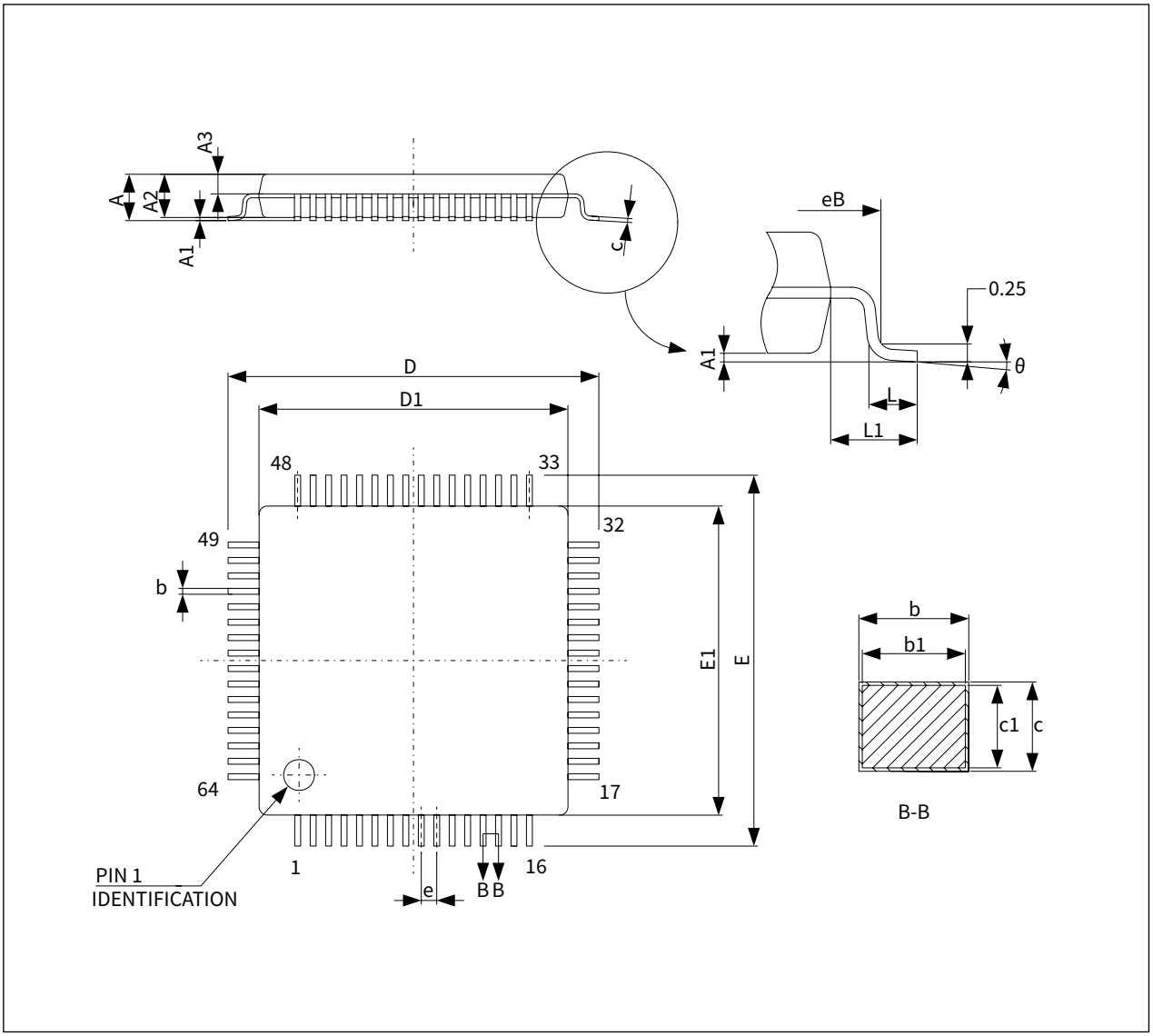


Caution 1: Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. CW is not responsible for any consequences resulting from such use. In no event will CW be liable for the customer using any of these engineering samples in production. CW's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

8.4 LQFP64 (7mm×7mm) package information

LQFP64 is a 64-pin, 7 x 7mm low-profile quad flat package.

Figure 8-7 LQFP64 (7mm×7mm) outline



Caution 1: Drawing is not to scale.

Table 8-4 LQFP64 (7mm×7mm) mechanical data

Symbol	Millimeters			Inches [1]		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
A3	0.590	0.640	0.690	0.0232	0.0252	0.0272
b	0.160	-	0.240	0.0063	-	0.0094
b1	0.150	0.180	0.210	0.0059	0.0071	0.0083
c	0.130	-	0.170	0.0051	-	0.0067
c1	0.120	0.130	0.140	0.0047	0.0051	0.0055
D	8.800	9.000	9.200	0.3465	0.3543	0.3622
D1	6.900	7.000	7.100	0.2717	0.2756	0.2795
E	8.800	9.000	9.200	0.3465	0.3543	0.3622
E1	6.900	7.000	7.100	0.2717	0.2756	0.2795
eB	8.100	-	8.250	0.3189	-	0.3248
e	0.400BSC			0.0157BSC		
L	0.450	-	0.750	0.0177	-	0.0295
L1	1.000REF			0.0394REF		
ccc	0	-	7°	0	-	7°

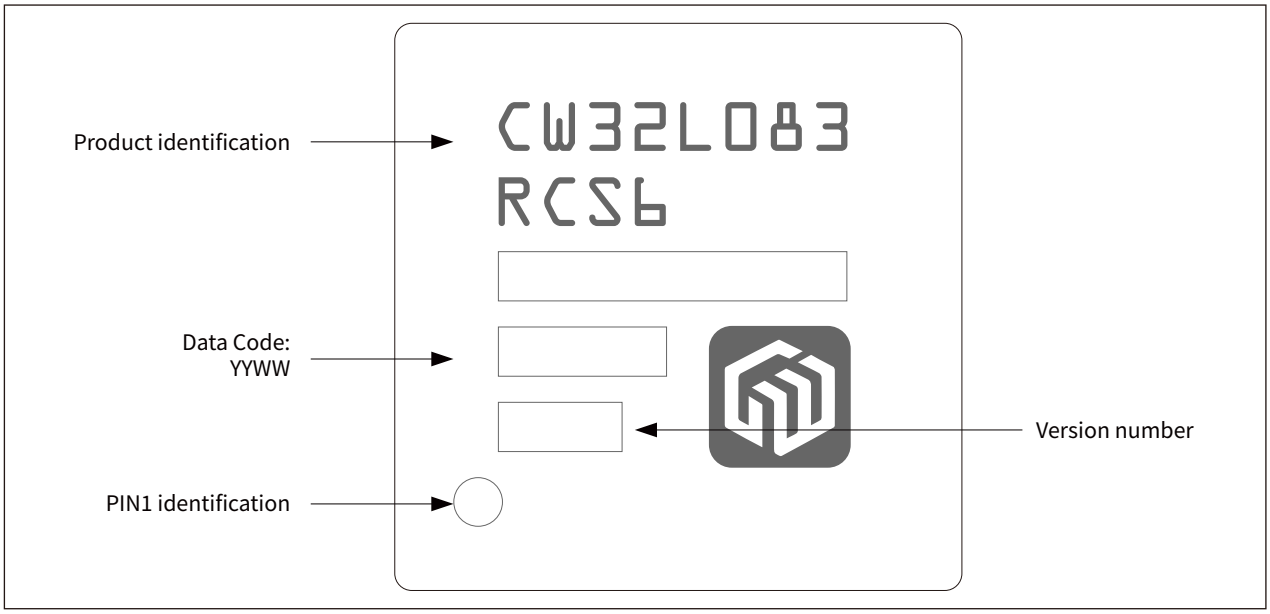
Caution 1: Values in inches are converted from mm and rounded to 4 decimal digits.

Device marking

The following figure gives an example of topside marking orientation versus pin 1 identifier location.

The printed markings may differ depending on the supply chain. Other optional marking or inset/upset marks, which identify the parts throughout supply chain operations, are not indicated below.

Figure 8-8 LQFP64 (7mm×7mm) topside marking example



Caution 1: Parts marked as ES or E or accompanied by an Engineering Sample notification letter are not yet qualified and therefore not approved for use in production. CW is not responsible for any consequences resulting from such use. In no event will CW be liable for the customer using any of these engineering samples in production. CW's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

8.5 Thermal characteristics

The maximum chip junction temperature $T_J$max must never exceed the values given in *Table 7-3 Thermal characteristics*.

The maximum chip-junction temperature, $T_J$max, in degrees Celsius, may be calculated using the following equation:

$$T_J\text{max} = T_A\text{max} + (P_D\text{max} \times \Theta_{JA})$$

Where:

- $T_A$max is the maximum ambient temperature in °C
- Θ_{JA} is the package junction-to-ambient thermal resistance, in °C /W
- $P_D$max is the sum of P_{INT}max and $P_{I/O}$max ($P_D$max = P_{INT}max + $P_{I/O}$max)
- P_{INT}max is the product of I_{DD} and V_{DD}, expressed in Watts. This is the maximum chip internal power
- $P_{I/O}$max represents the maximum power dissipation on output pins, where:

$$P_{I/O}\text{max} = \Sigma\ (V_{OL} \times I_{OL}) + \Sigma\ ((V_{DD} - V_{OH}) \times I_{OH})$$

The actual level and current conditions of the I/Os need to be included in the accurate calculation.

Table 8-5 Package thermal characteristics

Symbol	Parameter	Value	Unit
Θ_{JA}	Thermal resistance junction-ambient LQFP100 – 14mm X 14mm	41	°C /W
	Thermal resistance junction-ambient LQFP64 – 10mm X 10mm	46	

8.5.1 Reference document

JESD51-2 Integrated Circuits Thermal Test Method Environment Conditions – Natural Convection (Still Air). Available from *www.jedec.org*

9 Ordering information

Example: CW32L083VCT6x

Device family
CW32=ARM-based

Product type
L=Lower power

Sub-family
083=CW32L083xx

Pin count
K=32 pins
C=48 pins
R=64 pins
M=80 pins
V=100 pins

Code size
8=64Kbytes Flash
B=128Kbytes Flash
Z=192Kbytes Flash
C=256Kbytes Flash

Package
T/S=LQFP

Temperature range
6=-40°C~85°C
7=-40°C~105°C

Option
xxx=Programmed part
TR=Tape and reel

Table 9-1 Minimum Order Quantity (MOQ)

MCU	Packaging	Quantity	MOQ	MSL	Note
CW32L083VCT6	Tray	90 pcs/tray	900 pcs	3	10 trays/box, 6 boxes/carton, single box vacuumized
CW32L083MCT6	Tray	119 pcs/tray	1190 pcs	3	10 trays/box, 6 boxes/carton, single box vacuumized
CW32L083RBT6	Tray	160 pcs/tray	1600 pcs	3	10 trays/box, 6 boxes/carton, single box vacuumized
CW32L083RCT6	Tray	160 pcs/tray	1600 pcs	3	10 trays/box, 6 boxes/carton, single box vacuumized
CW32L083RCS6	Tray	250 pcs/tray	2500 pcs	3	10 trays/box, 6 boxes/carton, single box vacuumized

10 Revision history

Table 10-1 Document revision history

Date	Revision	Changes
October 19, 2022	Rev 1.0	Initial release.